Total Ionizing Dose Test Report

No. 18T-RTAX2000S-CQ352-DC9RF1

April 30, 2018

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TOTAL IONIZING DOSE TEST REPORT

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I. Summary Table

Parameter	Tolerance
1. Gross Functionality	Passed 300 krad (SiO_2)
2. Power Supply Current (ICCA/ICCI)	Passed 300 krad (SiO_2)
3. Input Threshold (VTIL/VIH)	Passed 300 krad (SiO_2)
4. Output Drive (VOL/VOH)	Passed 300 krad (SiO_2)
5. Propagation Delay	Passed 300 krad (SiO_2) for 10% degradation criterion
6. Transition Characteristics	Passed 300 krad (SiO_2)

II. Total Ionizing Dose (TID) Testing

This testing is designed on the base of an extensive database (see TID data of antifuse-based FPGAs at http://www.klabs.org and http://www.microsemi.com/soc) accumulated from the TID testing of many generations of antifuse-based FPGAs.

A. Device-Under-Test (DUT) and Irradiation Parameters

Table 1 lists the DUT and irradiation parameters. During irradiation, each input and most of the output is grounded through a 1 MΩ resistor; during annealing, each input or output is tied to the ground or VCCI with a 2.7 kΩ resistor. Appendix A contains the schematics of the irradiation-bias circuit.

Table 1 DUT and Irradiation Parameters

Part Number	RTAX2000S
Package	CQ352
Foundry	United Microelectronics Corp.
Technology	0.15 µm CMOS
DUT Design	TOP_AX2000S_TID
Die Lot Number	DC9RF1
Quantity Tested	6
Serial Number	300 krad(SiO2): 17185, 17207 200 krad(SiO2): 17182, 17183 100 krad(SiO2): 17175, 17179
Radiation Facility	Defense Microelectronics Activity
Radiation Source	Co-60
Dose Rate (±5%)	10 krad(SiO2)/min
Irradiation Temperature	Room
Irradiation and Measurement Bias (VCCI/VCCA)	Static at 3.3 V/1.5 V

B. Test Method

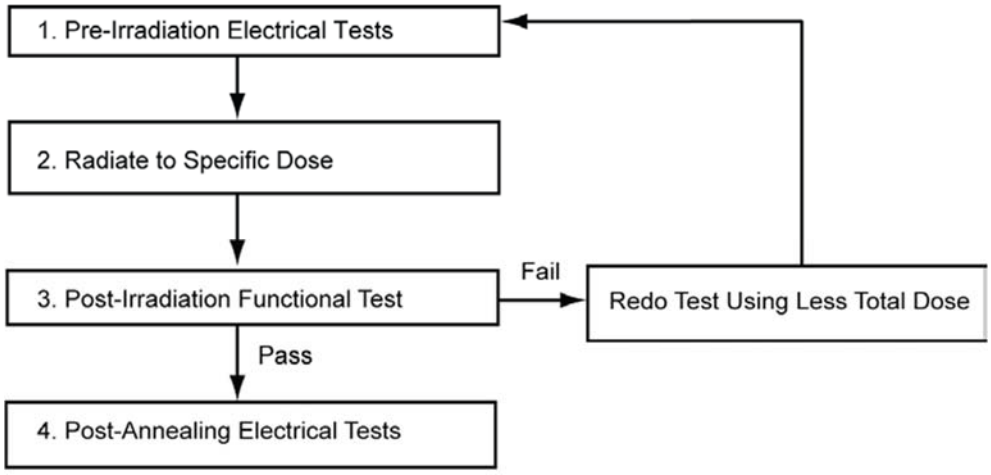


Figure 1 Parametric Test Flow Chart

The test method generally follows the guidelines in the military standard TM1019.8. Figure 1 is the flow chart describing the steps for functional and parametric tests, irradiation, and post-irradiation annealing.

The accelerated aging, or rebound test mentioned in TM1019.8, is unnecessary; because there is no adverse time-dependent effect (TDE) in Microsemi products manufactured by deep sub-micron CMOS technologies. Elevated temperature annealing basically reduces the effects originating from radiation-induced leakage currents. As indicated by test data in the following sections, the predominant radiation effects in RTAX2000S are due to radiation-induced leakage currents.

Room temperature annealing is performed in this test; the duration is approximately 7 days.

C. Design and Parametric Measurements

The DUT uses a high utilization, generic design (TOP_AX2000S_TID) to evaluate total dose effects for typical space applications. Appendix B contains the schematics and Verilog files of this design.

Table 2 lists measured electrical parameters and the corresponding logic design. The functionality is measured on the output pin (O_BS) of a combinational buffer-string with 14,000 buffers, output pins (O_ANDP_CLKF, O_ORP_CLKF, O_FF_CLKF, O_ANDC_CLKF, O_ORC_CLKF, O_ANDP_CLKG, O_ORP_CLKG, O_FF_CLKG, O_ANDC_CLKG, O_ORC_CLKG, O_ANDP_CLKH, O_ORP_CLKH, O_FF_CLKH, O_ANDC_CLKH, O_ORC_CLKH, O_ANDP_HCLKA, O_ORP_HCLKA, O_FF_HCLKA, O_ANDC_HCLKA, and O_ORC_HCLKA) of four (4) shift registers with 10,728 bits total, and half of the output pins (OUTX0, OUTX1, OUTX2, OUTX3, OUTX4, OUTX5, OUTX6 and OUTX7) of the embedded RAM configured as 16K×16.

ICC is measured on the power supply of the logic-array (ICCA) and I/O (ICCI) respectively. The input logic threshold (VIL/VIH) is measured on single-ended inputs EN8, DA, IO_I1, IO_I2, IO_I3, IO_I4, IO_I5 and IO_I6, and also on differential inputs DIO_I1P, DIO_I2P, DIO_I3P, DIO_I4P, DIO_I5P, DIO_I6P and DIO_I7P. The differential inputs are configured as LVPECL instead of LVDS; because LVPECL using 3.3 VDC, is worse than LVDS which uses 2.5 VDC. During the measurement on the differential inputs, the N (negative) side of the differential pair is biased at 1.8 V. The output-drive voltage (VOL/VOH) is measured on QA0 and YQ0. The propagation delay is measured on the output (O_BS) of the buffer string; the definition is the time delay from the triggering edge at the CLOCK input to the switching edge at the output O_BS. Both the delays of low-to-high and high-to-low output transitions are measured; the reported delay is the average of these two measurements. The transition characteristics, measured on the output O_BS, are shown as oscilloscope captures.

Table 2 Logic Design for Parametric Measurements

Parameters	Logic Design
1. Functionality	All key logic functions (O_BS, O_ANDP_CLKF, O_ORP_CLKF, O_FF_CLKF, O_ANDC_CLKF, O_ORC_CLKF, O_ANDP_CLKG, O_ORP_CLKG, O_FF_CLKG, O_ANDC_CLKG, O_ORC_CLKG, O_ANDP_CLKH, O_ORP_CLKH, O_FF_CLKH, O_ANDC_CLKH, O_ORC_CLKH, O_ANDP_HCLKA, O_ORP_HCLKA, O_FF_HCLKA, O_ANDC_HCLKA, and O_ORC_HCLKA), and outputs of embedded RAM (OUTX0, OUTX1, OUTX2, OUTX3, OUTX4, OUTX5, OUTX6 and OUTX7)
2. ICC (ICCA/ICCI)	DUT power supply
3. Input Threshold (VIL/VIH)	Single ended inputs (EN8/YQ0, DA/QA0, IO_I1/IO_O1, IO_I2/IO_O2, IO_I3/IO_O3, IO_I4/IO_O4, IO_I5/IO_O5, IO_I6/IO_O6), and differential inputs (DIO_I1P/DIO_O1, DIO_I2P/DIO_O2, DIO_I3P/DIO_O3, DIO_I4P/DIO_O4, DIO_I5P/DIO_O5, DIO_I6P/DIO_O6, DIO_I7P/DIO_O7)
4. Output Drive (VOL/VOH)	Output buffer (EN8/YQ0, DA/QA0)
5. Propagation Delay	String of buffers (CLOCK to O_BS)
6. Transition Characteristic	String of buffers output (O_BS)

III. Test Results

A. Functionality

Every DUT passed the pre-irradiation and post-annealing functional tests. The as-irradiated DUT is functionally tested on the output (O_FF_HCLKA) of the largest shift register.

B. Power Supply Current (ICCA and ICCI)

Figure 2 through Figure 7 plot the influx standby ICCA and ICCI versus total dose for each DUT. The post-annealing ICC for four different bit patterns, all '0', all '1', checkerboard and inverted-checkerboard, in the RAM are basically the same.

In compliance with TM1019.8 subsection 3.11.2.c, the post-irradiation-parametric limit (PIPL) for the post-annealing ICCI in this test is defined as the addition of highest ICCI, ICCDA and ICCDIFFA values in Table 2-4 of *the RTAX-S/SL and RTAX-DSP Radiation-Tolerant FPGAs* datasheet:

http://www.microsemi.com/soc/documents/RTAXS_DS.pdf

For ICCA, the PIPL is 500 mA; the PIPL of ICCI equals to 35 + 10 + 3.13 × 7 = 66.91 (mA). Note that there are 7 pairs of differential LVPECL inputs in each DUT.

Table 3 summarizes the pre-irradiation, post-irradiation right after irradiation and before anneal, and post-annealing ICCA and ICCI data.

Table 3 Pre-Irradiation, Post Irradiation and Post-Annealing ICC

DUT	Total Dose	ICCA (mA)			ICCI (mA)		
		Pre-irrad	Post-irrad	Post-ann	Pre-irrad	Post-irrad	Post-ann
17175	100 krad	7.9	8	7.8	90.1	91.9	89.7
17179	100 krad	3.0	3	2.7	27.3	28.6	27.7
17182	200 krad	3.2	6.2	2.9	27.4	58.7	38.8
17183	200 krad	1.2	3.2	1.2	27.2	54	36.8
17185	300 krad	2.3	85.1	10.9	27.2	140	60.1
17207	300 krad	1.5	86.8	7.2	27.5	125	55.6

Based on these PIPL, post-annealed DUT passes both the ICCA and ICCI spec for 300 krad (SiO2).

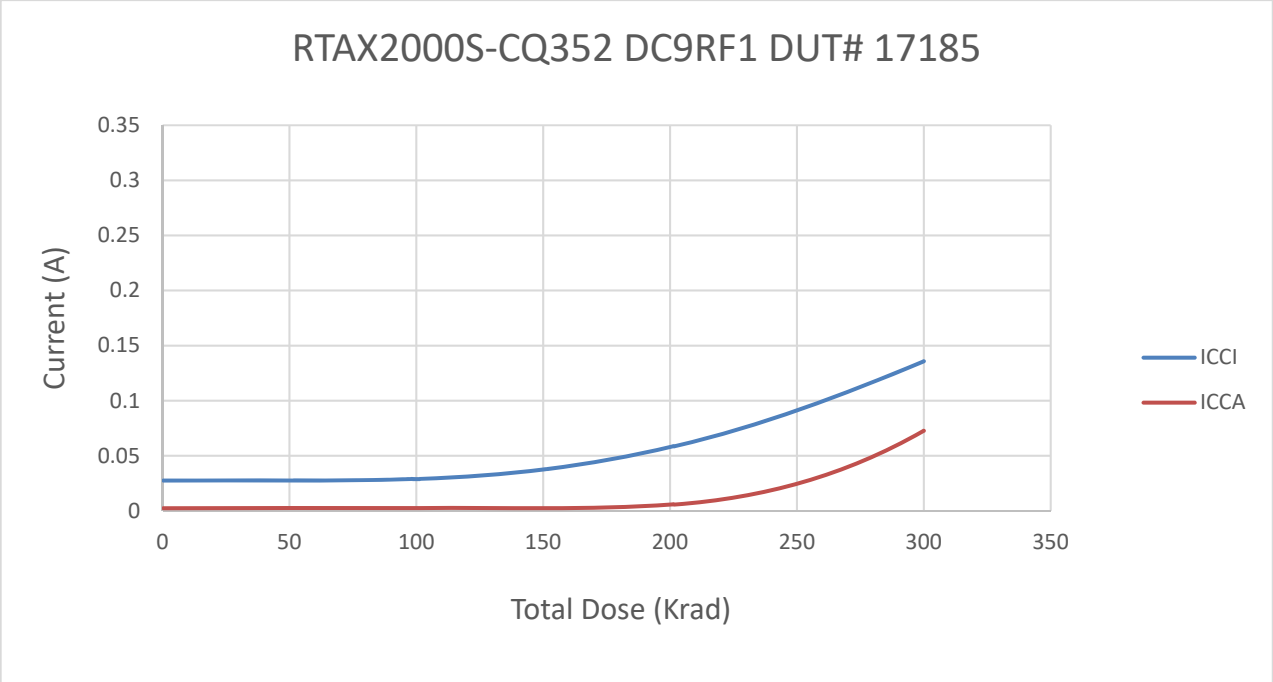


Figure 2 DUT 17185 Influx ICCA and ICCI

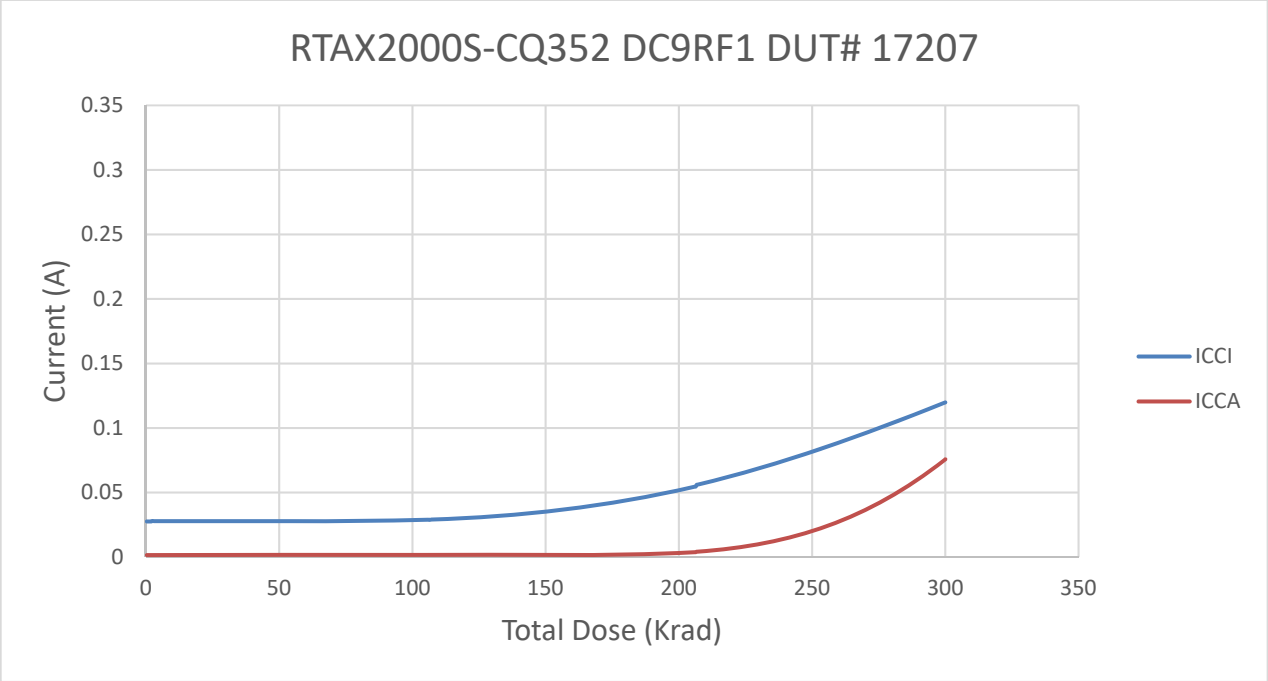


Figure 3 DUT 17207 Influx ICCA and ICCI

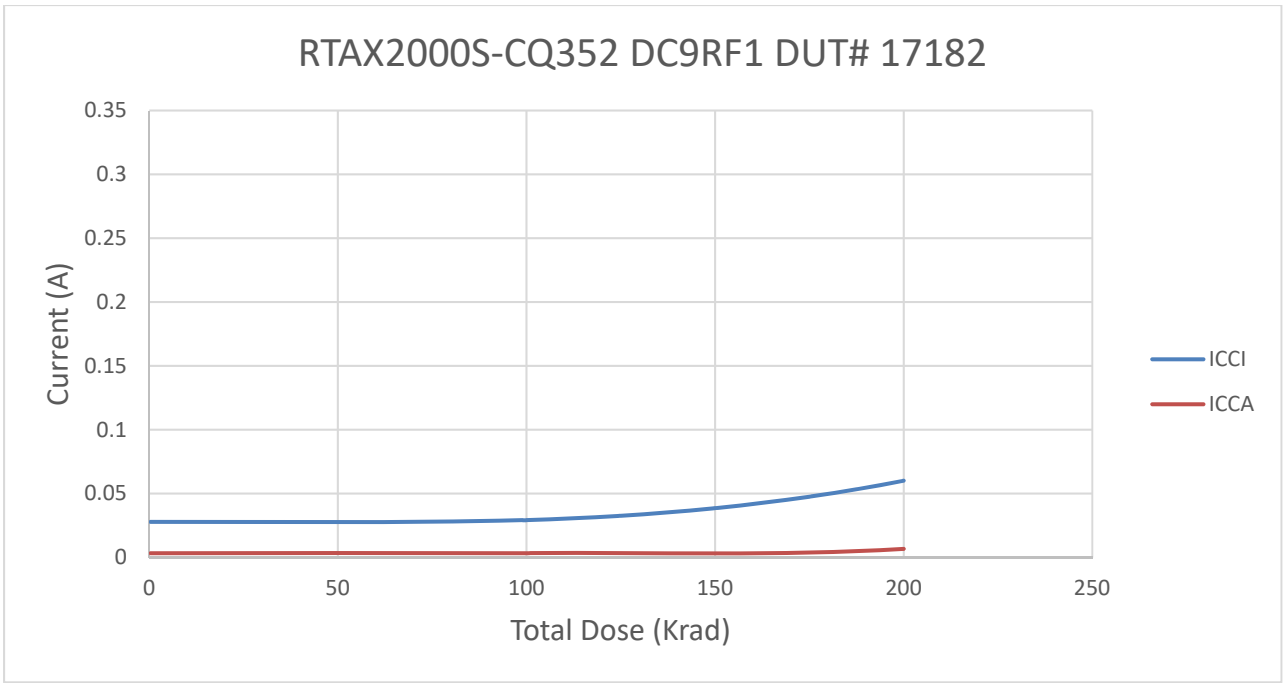


Figure 4 DUT 17182 Influx ICCA and ICCI

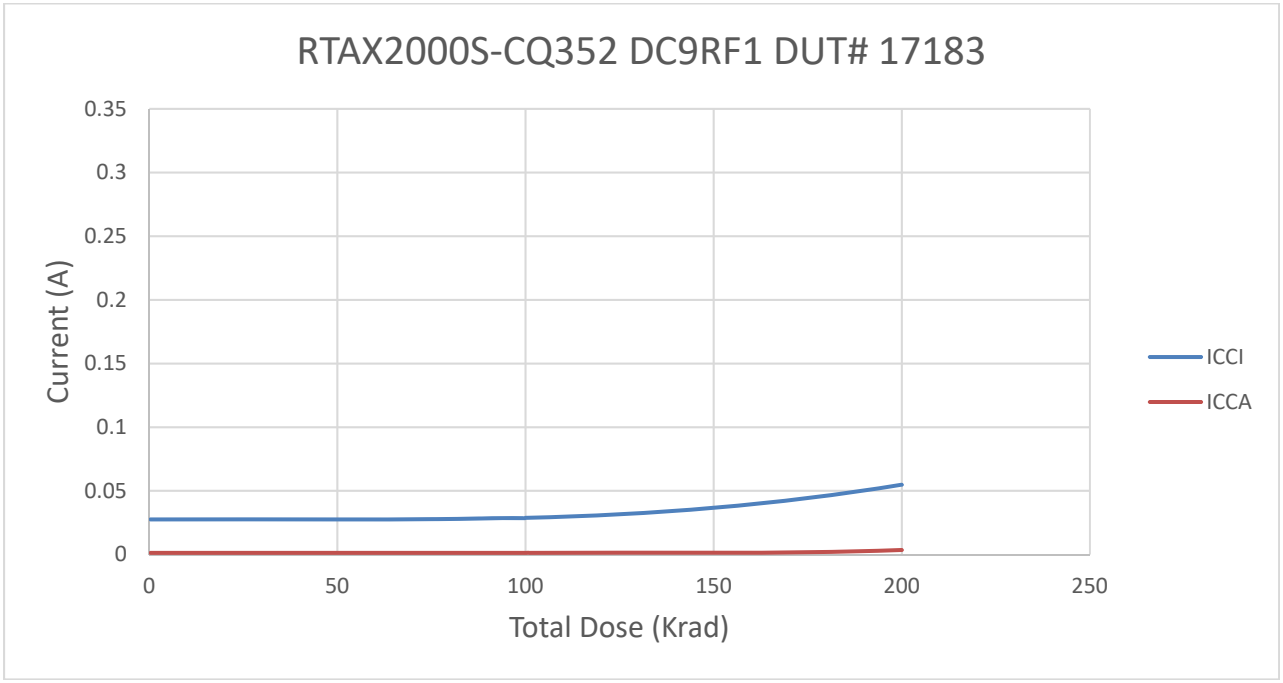


Figure 5 DUT 17183 Influx ICCA and ICCI

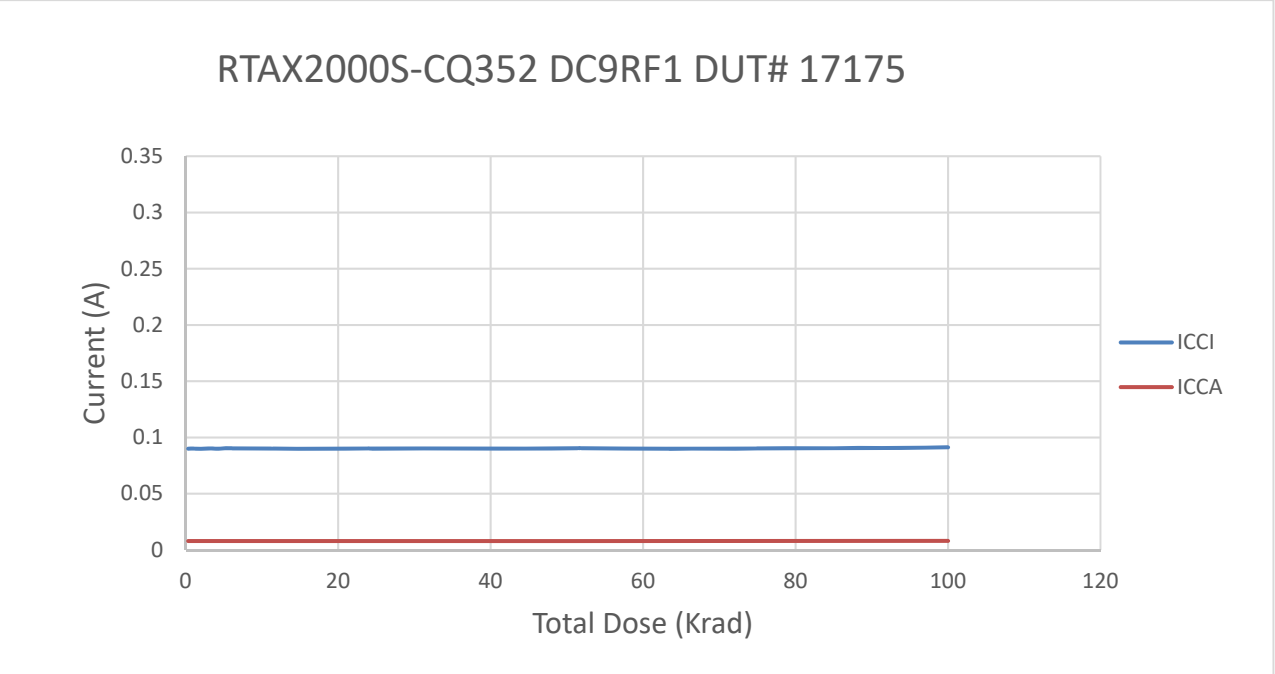


Figure 6 DUT 17175 Influx ICCA and ICCI

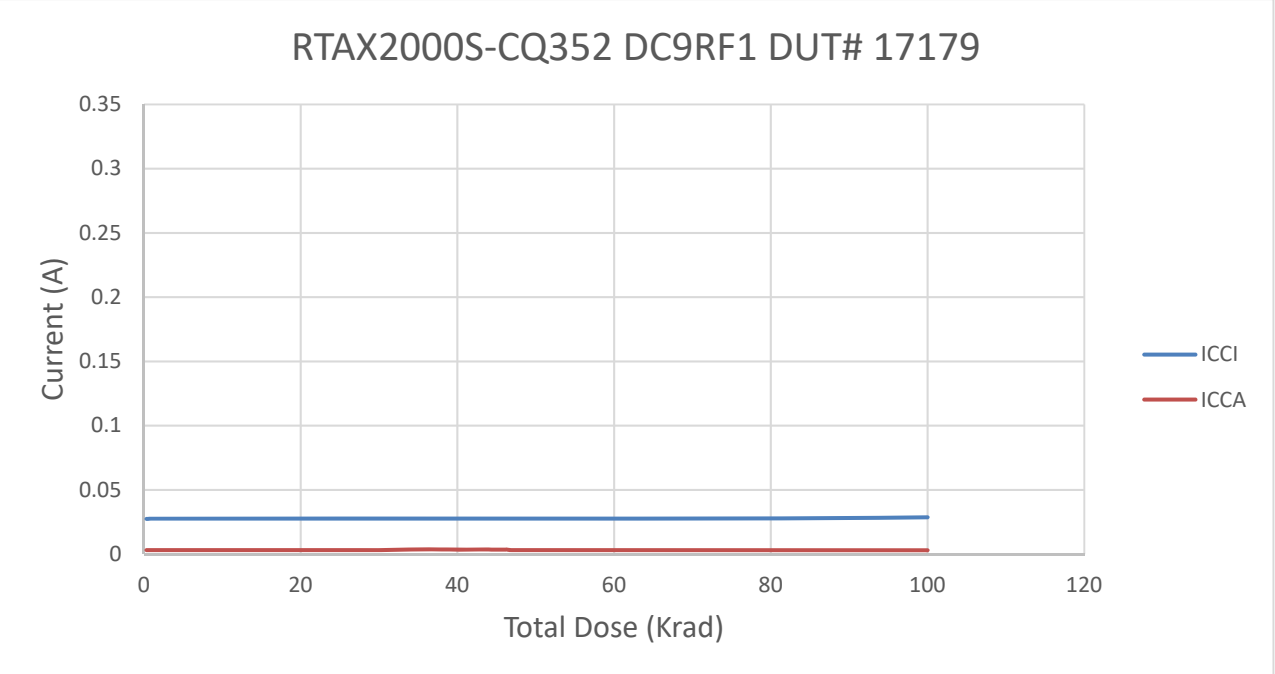


Figure 7 DUT 17179 Influx ICCA and ICCI

C. Single-Ended Input Logic Threshold (VIL/VIH)

Table 4a through Table 4c list the pre-irradiation and post-annealing single-ended input logic thresholds. All data are within the specification limits. The post-annealing shift in every case is very small.

Table 4a Pre-Irradiation and Post-Annealing Input Thresholds

DUT	17185 (300 krad)				17207 (300 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DA	1410	1390	1380	1370	1395	1375	1370	1365
EN8	1390	1360	1375	1370	1365	1365	1370	1365
IO_I_6	1400	1370	1370	1365	1375	1375	1370	1370
IO_I_5	1395	1365	1390	1385	1370	1365	1385	1375
IO_I_4	1380	1365	1385	1370	1370	1370	1380	1370
IO_I_3	1340	1330	1410	1390	1335	1325	1405	1390
IO_I_2	1375	1365	1395	1390	1365	1355	1390	1380
IO_I_1	1370	1365	1390	1385	1370	1360	1385	1380

Table 4b Pre-Irradiation and Post-Annealing Input Thresholds

DUT	17182 (200 krad)				17183 (200 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DA	1400	1380	1370	1365	1395	1370	1370	1360
EN8	1385	1370	1375	1365	1365	1355	1370	1360
IO_I_6	1395	1365	1380	1370	1375	1360	1375	1365
IO_I_5	1385	1355	1385	1375	1365	1350	1380	1370
IO_I_4	1370	1365	1380	1375	1370	1360	1375	1365
IO_I_3	1335	1325	1395	1395	1330	1320	1390	1390
IO_I_2	1370	1360	1390	1385	1365	1355	1390	1380
IO_I_1	1365	1355	1385	1380	1370	1355	1385	1375

Table 4c Pre-Irradiation and Post-Annealing Input Thresholds

DUT	17175 (100 krad)				17179 (100 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DA	1400	1385	1375	1370	1405	1390	1380	1375
EN8	1385	1365	1380	1370	1390	1365	1375	1365
IO_I_6	1395	1375	1380	1375	1395	1375	1380	1375
IO_I_5	1395	1365	1385	1380	1390	1365	1385	1380
IO_I_4	1385	1365	1385	1380	1375	1370	1380	1380
IO_I_3	1340	1330	1405	1400	1335	1330	1405	1400
IO_I_2	1375	1365	1395	1390	1375	1370	1395	1390
IO_I_1	1370	1365	1390	1385	1370	1365	1390	1385

D. Differential Input (LVPECL) Threshold Voltage (VIL/VIH)

Table 5a through Table 5c list the LVPECL differential input threshold voltage changes due to irradiations. All pins show negligible changes, and all the data are within the specification.

Table 5a Pre-Irradiation and Post-Annealing Differential Input Thresholds

DUT	17185 (300 krad)				17207 (300 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DIO_IP_1	1795	1795	1790	1790	1790	1790	1785	1785
DIO_IP_2	1790	1790	1790	1790	1800	1795	1795	1800
DIO_IP_3	1800	1800	1795	1795	1795	1795	1790	1790
DIO_IP_4	1785	1785	1790	1790	1785	1785	1790	1790
DIO_IP_5	1790	1790	1790	1790	1795	1795	1795	1795
DIO_IP_6	1785	1785	1785	1785	1780	1780	1785	1785
DIO_IP_7	1790	1790	1790	1790	1785	1785	1785	1785

Table 5b Pre-Irradiation and Post-Annealing Differential Input Thresholds

DUT	17182 (200 krad)				17183 (200 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DIO_IP_1	1790	1790	1790	1785	1795	1795	1790	1790
DIO_IP_2	1795	1790	1795	1795	1790	1785	1790	1790
DIO_IP_3	1790	1790	1780	1785	1795	1795	1790	1790
DIO_IP_4	1780	1780	1790	1790	1780	1780	1785	1790
DIO_IP_5	1795	1795	1790	1790	1800	1800	1795	1795
DIO_IP_6	1790	1790	1795	1795	1785	1780	1790	1790
DIO_IP_7	1795	1795	1795	1795	1790	1790	1790	1790

Table 5c Pre-Irradiation and Post-Annealing Differential Input Thresholds

DUT	17175 (100 krad)				17179 (100 krad)			
Input Pin	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann	Pre-Irrad	Post-Ann
	VIL (mV)		VIH (mV)		VIL (mV)		VIH (mV)	
DIO_IP_1	1795	1795	1790	1790	1800	1800	1795	1795
DIO_IP_2	1790	1785	1790	1790	1790	1790	1790	1795
DIO_IP_3	1790	1795	1785	1790	1795	1800	1790	1790
DIO_IP_4	1785	1790	1790	1795	1785	1785	1790	1790
DIO_IP_5	1790	1795	1790	1790	1790	1790	1790	1790
DIO_IP_6	1790	1785	1790	1790	1780	1785	1785	1790
DIO_IP_7	1790	1790	1790	1790	1805	1805	1800	1800

E. Output-Drive Voltage (VOL/VOH)

The pre-irradiation and post-annealing VOL/VOH are listed in Tables 6 and 7. The post-annealing data are within the specification limits.

Table 6 Pre-Irradiation and Post-Annealing VOL (mV) at Various Sinking Current

Sourcing Current	Pin\DUT	17185 (300 krad)		17207 (300 krad)		17182 (200 krad)		17183 (200 krad)		17175 (100 krad)		17179 (100 krad)	
		Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an
1 mA	QA0	9	8	9	8	9	8	9	8	9	8	9	8
	YQ0	9	9	9	11	9	9	9	10	9	10	9	10
12 mA	QA0	105	94	101	92	100	89	103	92	104	94	104	93
	YQ0	108	112	104	122	101	107	105	118	105	111	106	112
20 mA	QA0	175	157	169	153	167	150	172	154	174	157	173	155
	YQ0	180	187	173	202	169	179	175	196	176	186	177	188
50 mA	QA0	444	399	430	388	424	380	437	391	442	398	439	396
	YQ0	456	474	439	534	429	455	446	494	447	471	449	476
100 mA	QA0	938	844	909	820	896	805	924	828	935	845	927	836
	YQ0	962	996	927	1055	907	956	941	1030	943	991	946	1002

Table 7 Pre-Irradiation and Post-Annealing VOH (mV) at Various Sourcing Current

Sourcing Current	Pin\DUT	17185 (300 krad)		17207 (300 krad)		17182 (200 krad)		17183 (200 krad)		17175 (100 krad)		17179 (100 krad)	
		Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an	Pre-rad	Post-an
1 mA	QA0	3286	3285	3287	3284	3287	3286	3287	3286	3287	3287	3287	3287
	YQ0	3288	3283	3288	3284	3288	3285	3287	3285	3287	3286	3287	3286
8 mA	QA0	3211	3213	3213	3215	3214	3218	3212	3216	3212	3217	3212	3218
	YQ0	3211	3203	3213	3192	3215	3207	3212	3204	3213	3207	3212	3206
20 mA	QA0	3081	3089	3084	3092	3088	3098	3081	3094	3081	3095	3082	3095
	YQ0	3078	3063	3084	3056	3089	3072	3081	3063	3083	3069	3080	3066
50 mA	QA0	2739	2764	2746	2771	2756	2783	2741	2771	2740	2772	2742	2775
	YQ0	2733	2696	2744	2694	2757	2719	2738	2696	2741	2709	2736	2703
100 mA	QA0	2079	2128	2091	2140	2110	2166	2079	2139	2075	2139	2090	2152
	YQ0	2067	1993	2088	1835	2114	2038	2073	1992	2081	2016	2074	2006

F. Propagation Delay

The propagation delay was measured in-situ, post-irradiation, and post-annealing. The results are plotted in Figure 8, and listed in Table 8. As shown in Figure 8, the propagation delay moves with the total dose, but the change is small throughout the irradiation. Referring to influx static current plots (Figure 2 through Figure 7), a device probably heats up as the dose increases. The rising temperature could be the root cause of the increasing trend at high doses. The post-annealing data, on the other hand, show decreased delay in every case.

The radiation delta in every case is well within the 10% degradation criterion. The user can take the worst case for the design margin consideration.

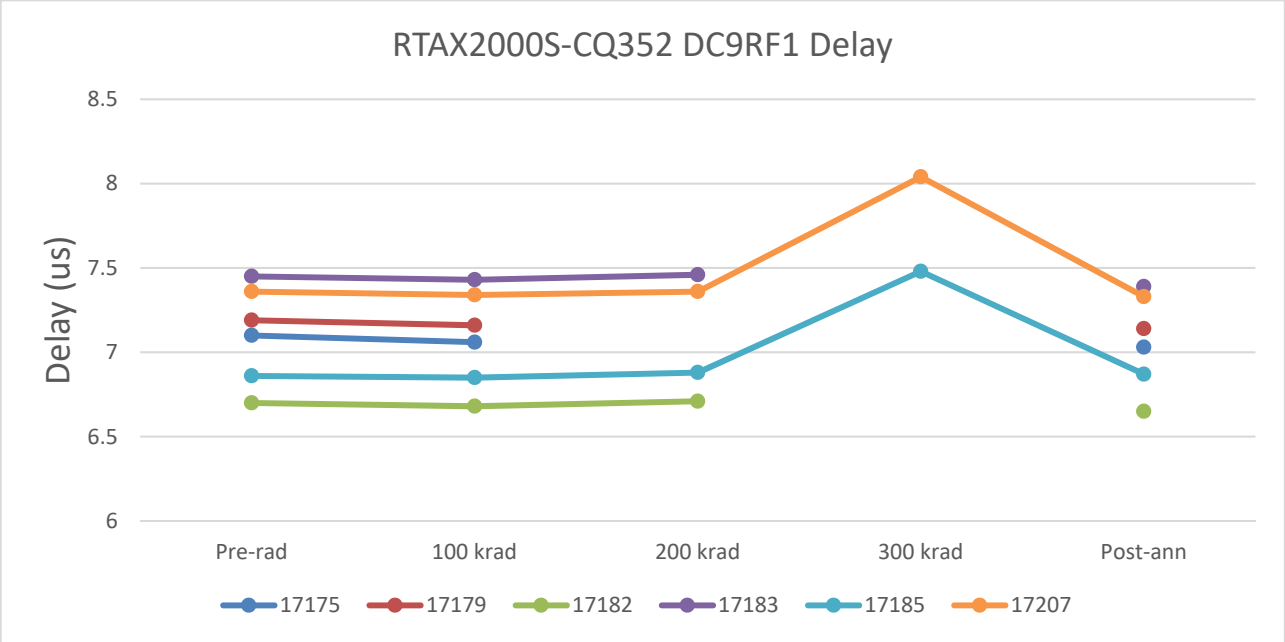


Figure 8 In-Situ Propagation Delay versus Total Dose

Table 8 Radiation-Induced Propagation Delay Degradations

Delay (µs)							
	DUT	**Total Dose**	**Pre-rad**	**100 krad**	**200 krad**	**300 krad**	**Post-ann**
	17175	100 krad	7.10	7.06	-	-	7.03
	17179	100 krad	7.19	7.16	-	-	7.14
	17182	200 krad	6.70	6.68	6.71	-	6.65
	17183	200 krad	7.45	7.43	7.46	-	7.39
	17185	300 krad	6.86	6.85	6.88	7.48	6.87
	17207	300 krad	7.36	7.34	7.36	8.04	7.33
Radiation Δ (%)							
	DUT	**Total Dose**	**Pre-rad**	**100 krad**	**200 krad**	**300 krad**	**Post-ann**
	17175	100 krad	-	-0.56 %	-	-	-0.99 %
	17179	100 krad	-	-0.42 %	-	-	-0.70 %
	17182	200 krad	-	-0.30 %	0.15 %	-	-0.75 %
	17183	200 krad	-	-0.27 %	0.13 %	-	-0.81 %
	17185	300 krad	-	-0.15 %	0.29 %	9.04 %	0.15 %
	17207	300 krad	-	-0.27 %	0.00 %	9.24 %	-0.41 %

G. Transition Characteristics

Figure 9a to Figure 20b show the pre-irradiation and post-annealing transition edges. In each case, the radiation-induced transition-time degradation is insignificant.

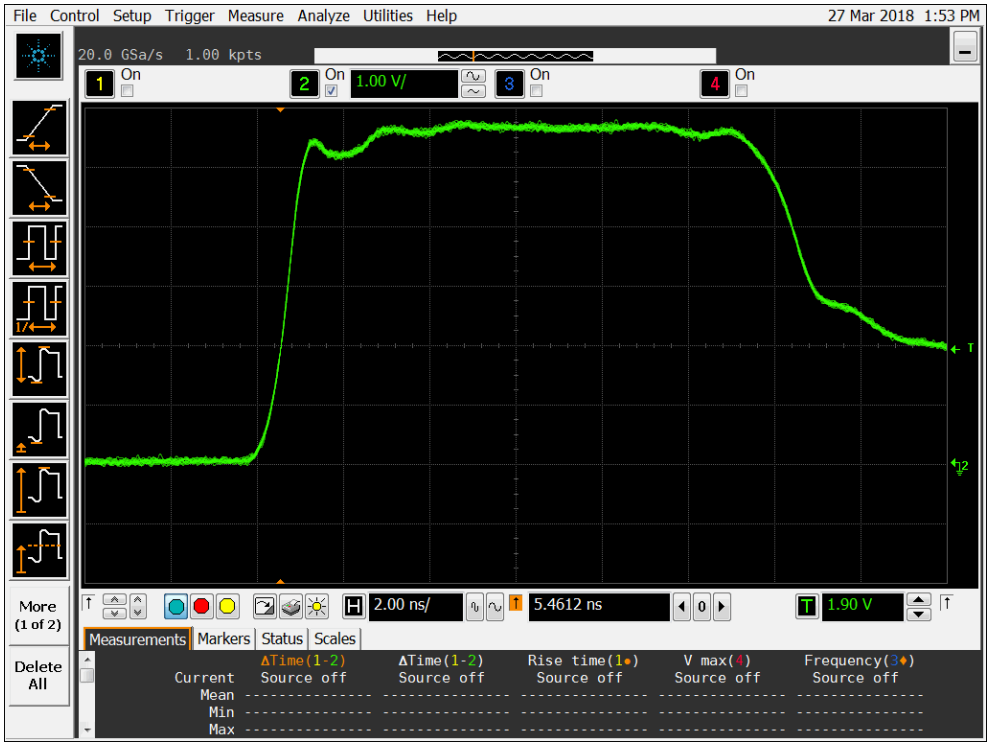


Figure 9a DUT 17185 Pre-Irradiation Rising Edge

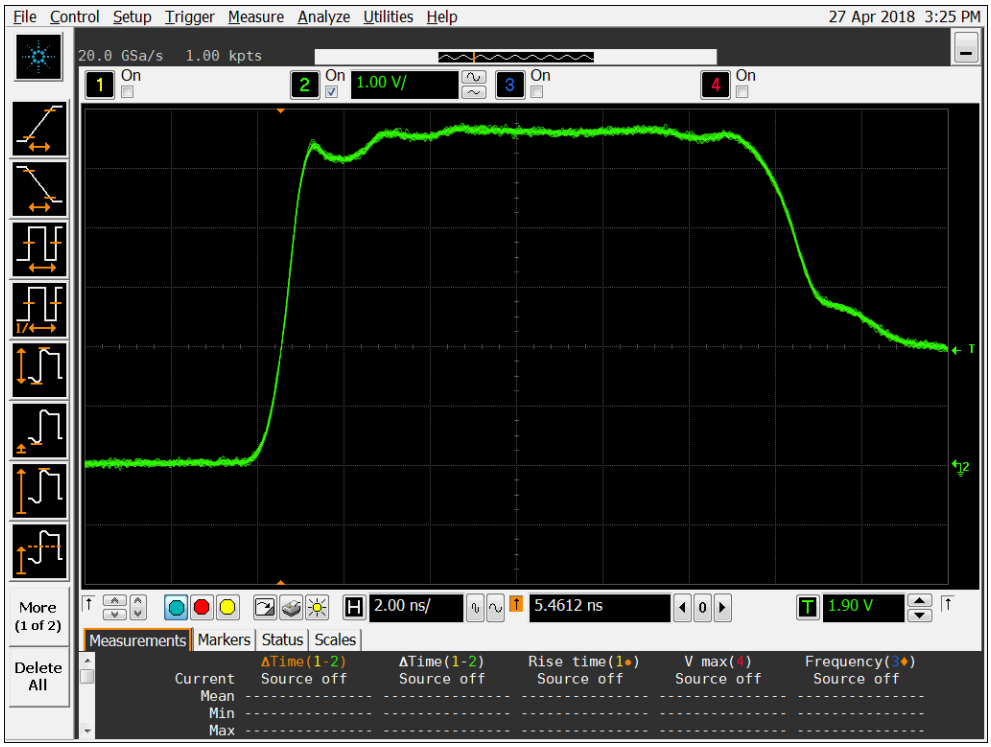


Figure 9b DUT 17185 Post-Annealing Rising Edge

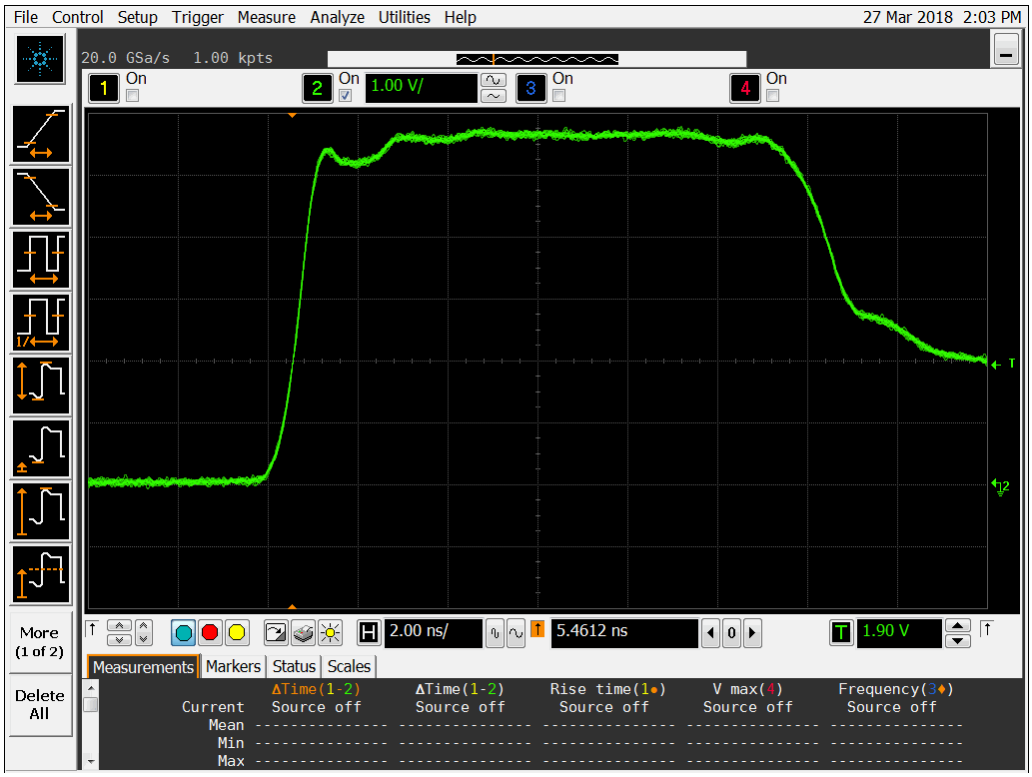


Figure 10a DUT 17207 Pre-Irradiation Rising Edge

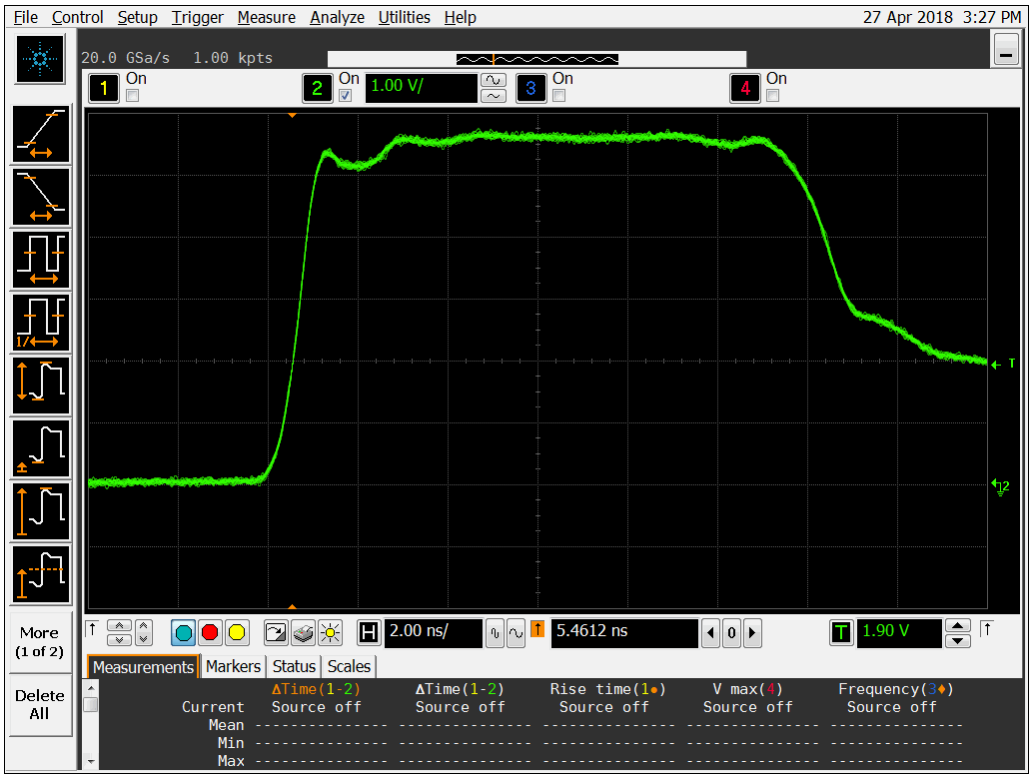


Figure 10b DUT 17207 Post-Annealing Rising Edge

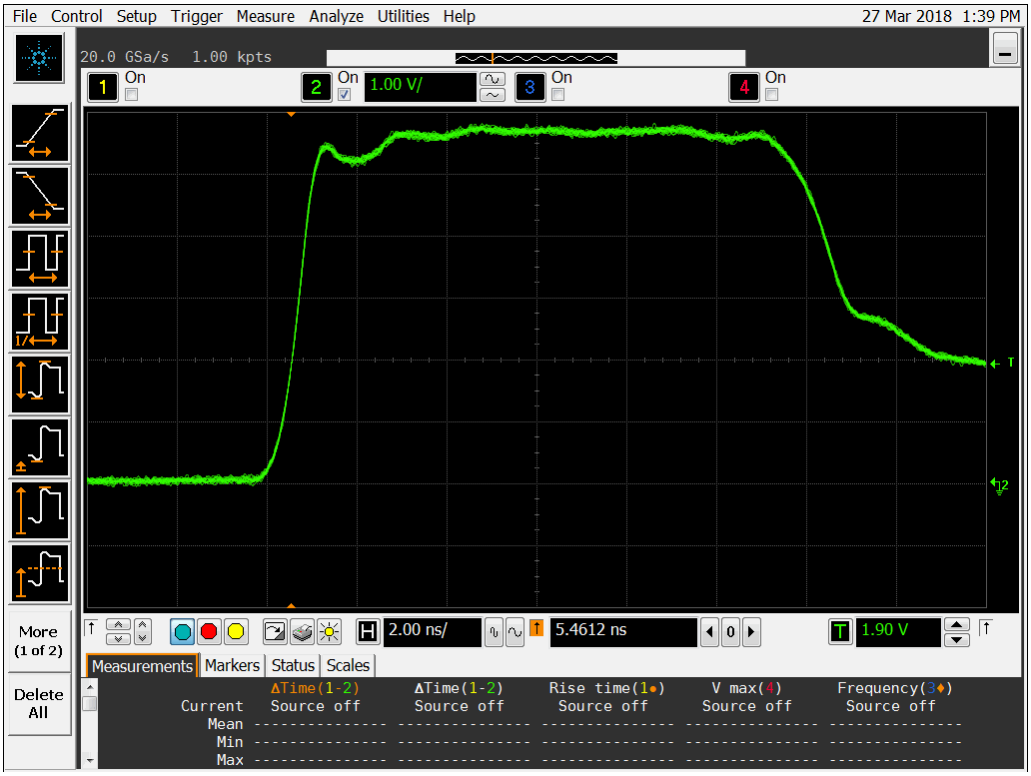


Figure 11a DUT 17182 Pre-Radiation Rising Edge



Figure 11b DUT 17182 Post-Annealing Rising edge

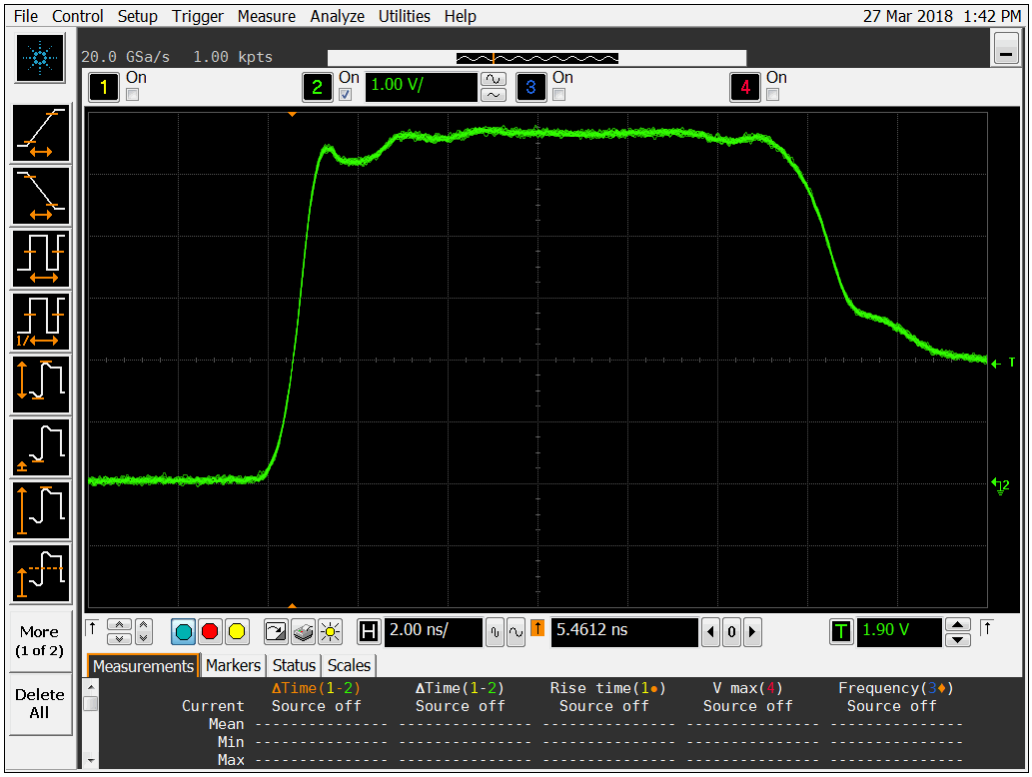


Figure 12a DUT 17183 Pre-Irradiation Rising Edge

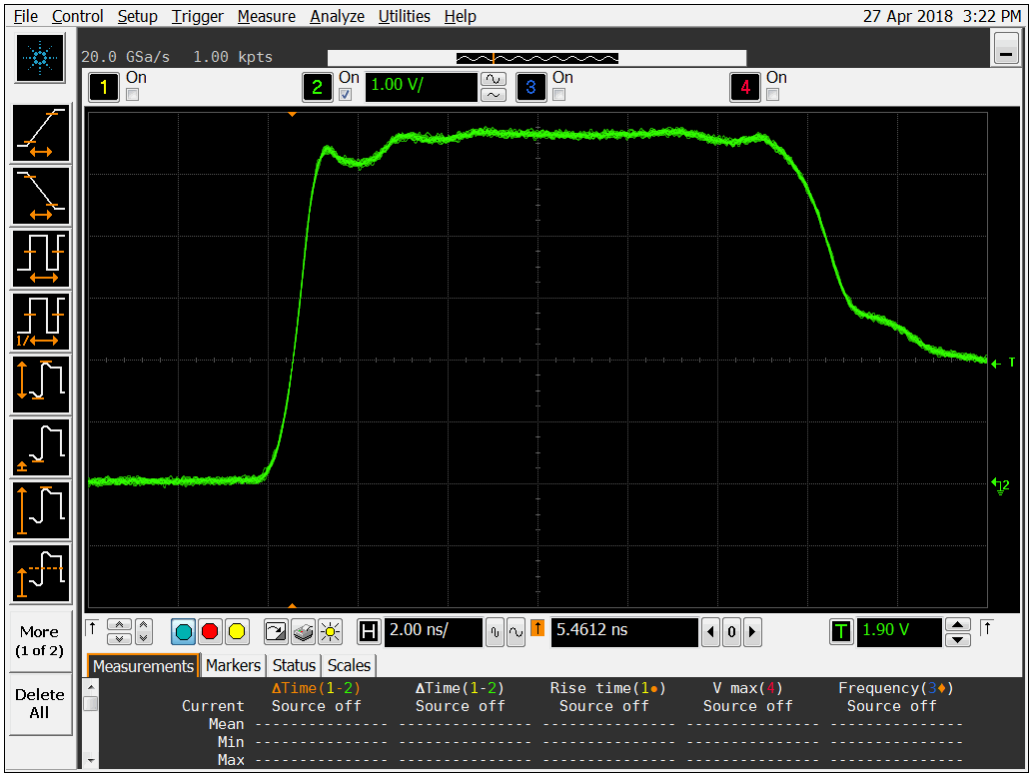


Figure 12b DUT 17183 Post-Annealing Rising Edge

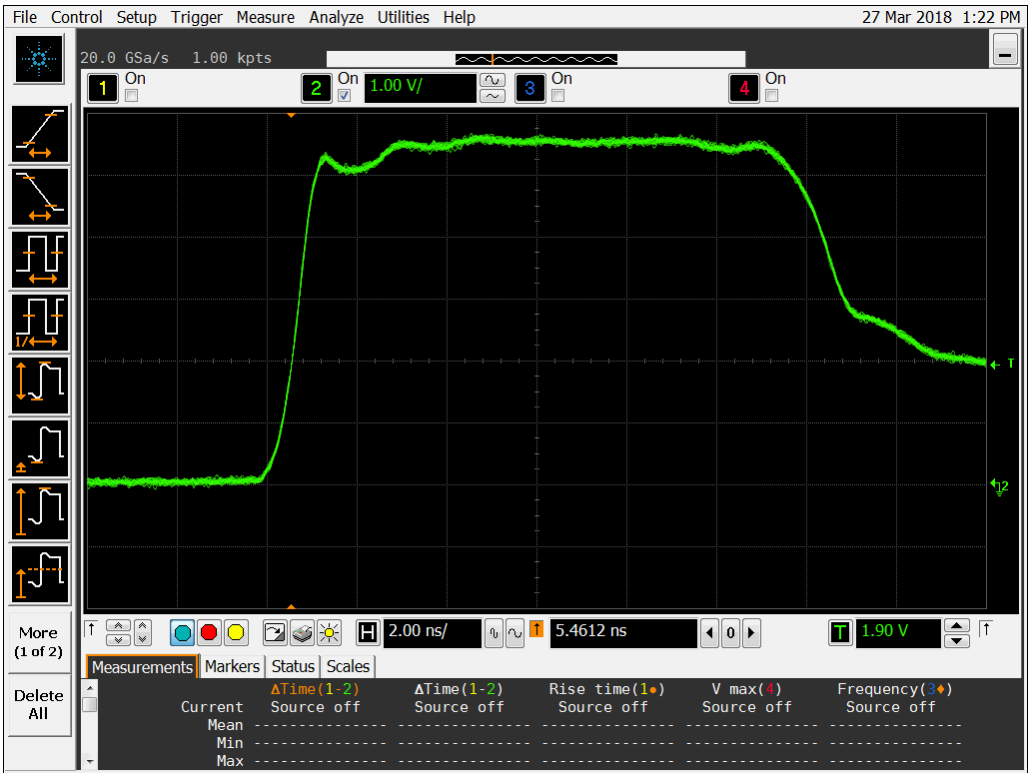


Figure 13a DUT 17175 Pre-Irradiation Rising Edge

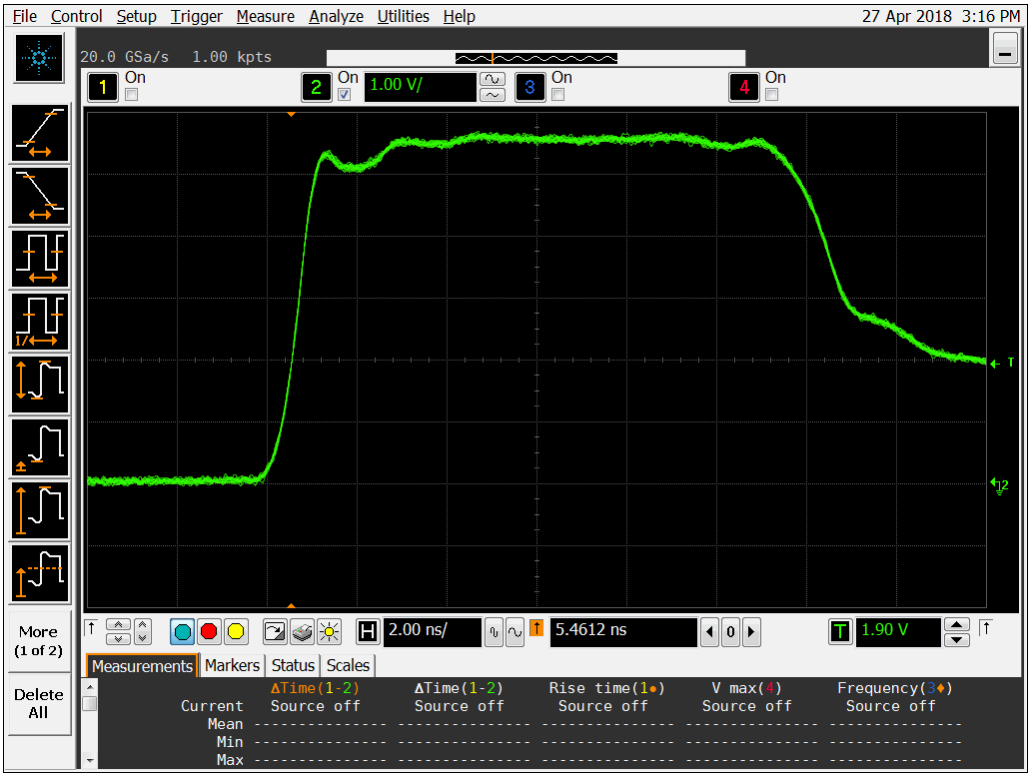


Figure 13b DUT 17175 Post-Annealing Rising Edge

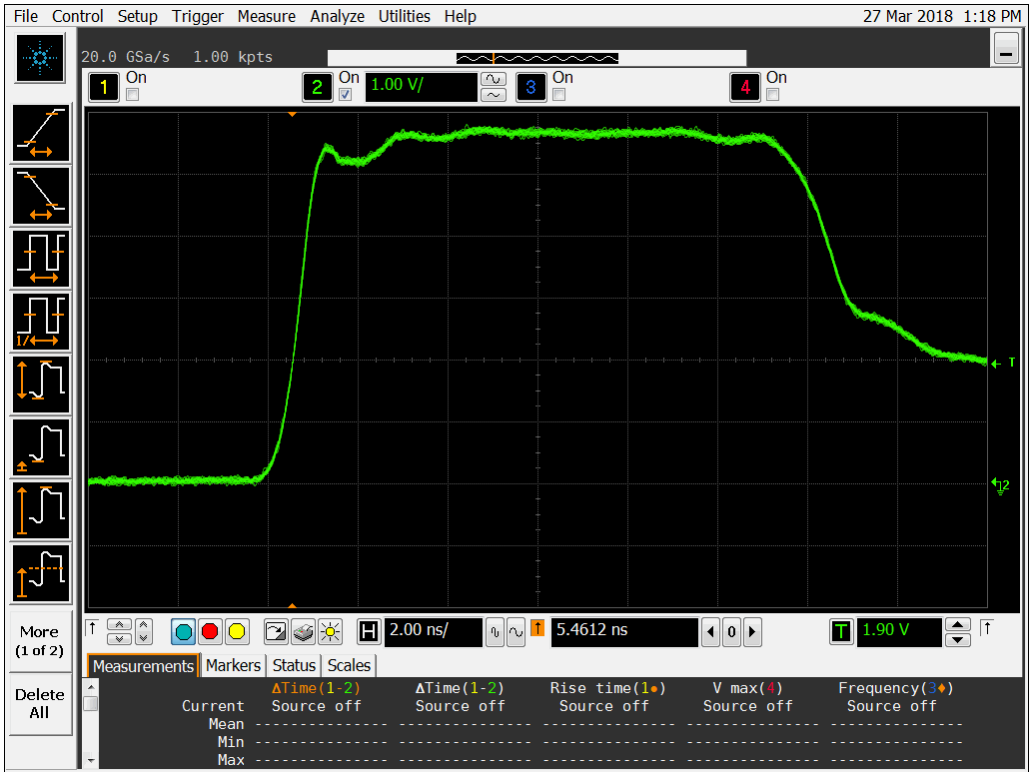


Figure 14a DUT 17179 Pre-Irradiation Rising Edge

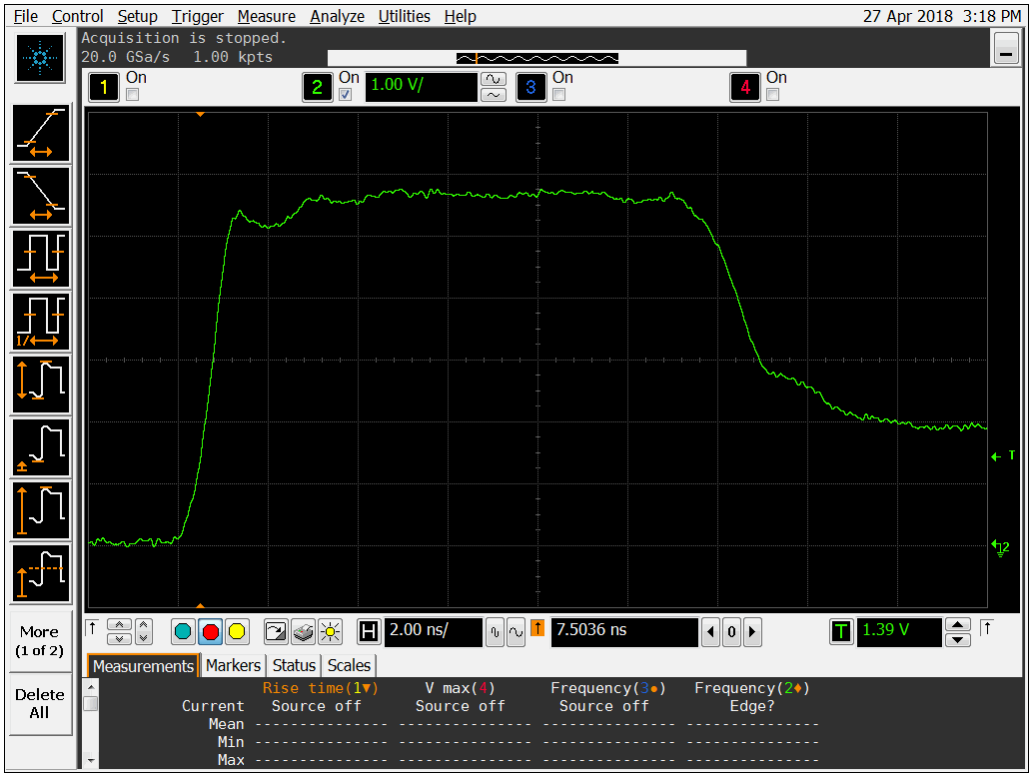


Figure 14b DUT 17179 Post-Annealing Rising Edge

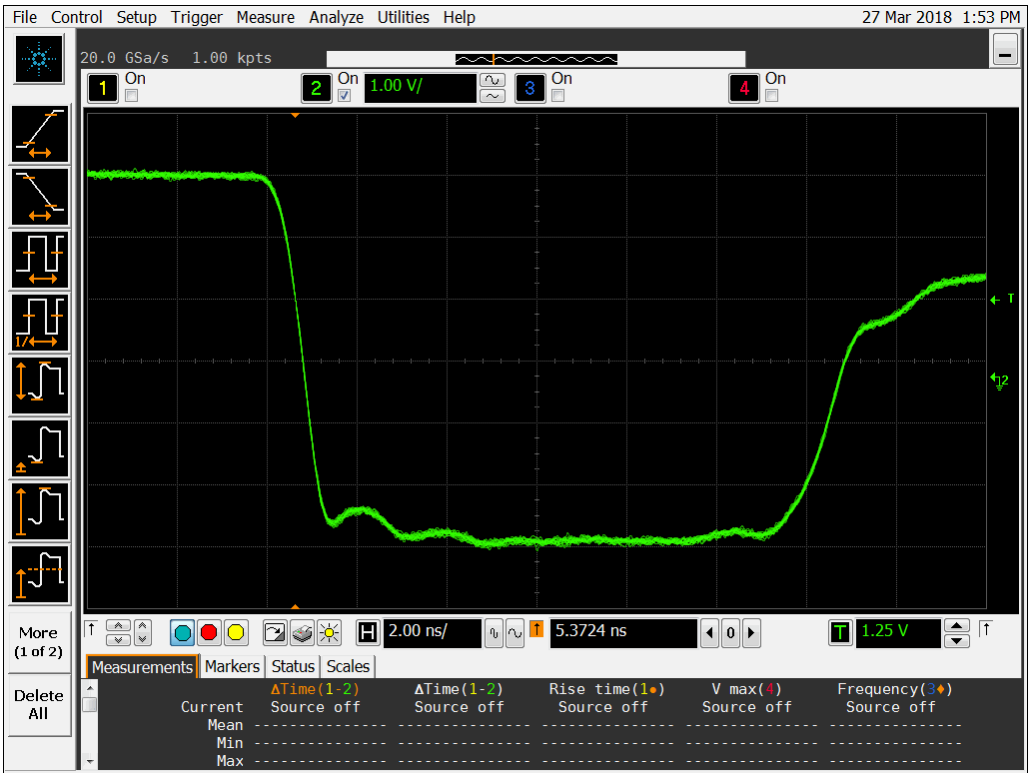


Figure 15a DUT 17185 Pre-Radiation Falling Edge

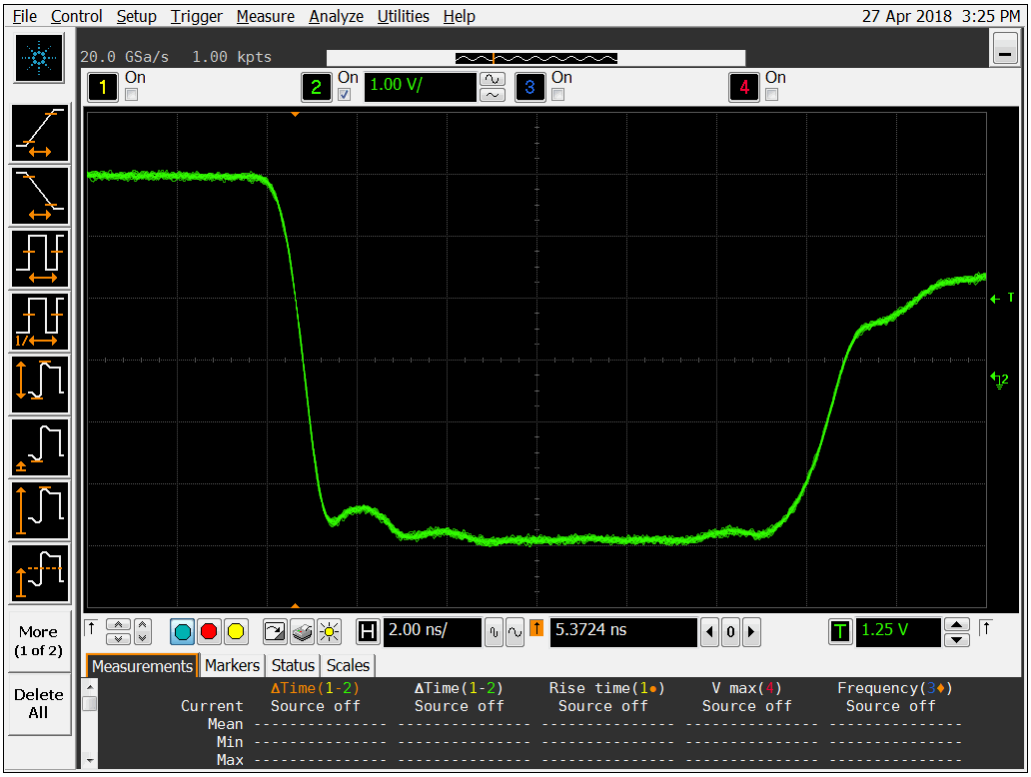


Figure 15b DUT 17185 Post-Annealing Falling Edge

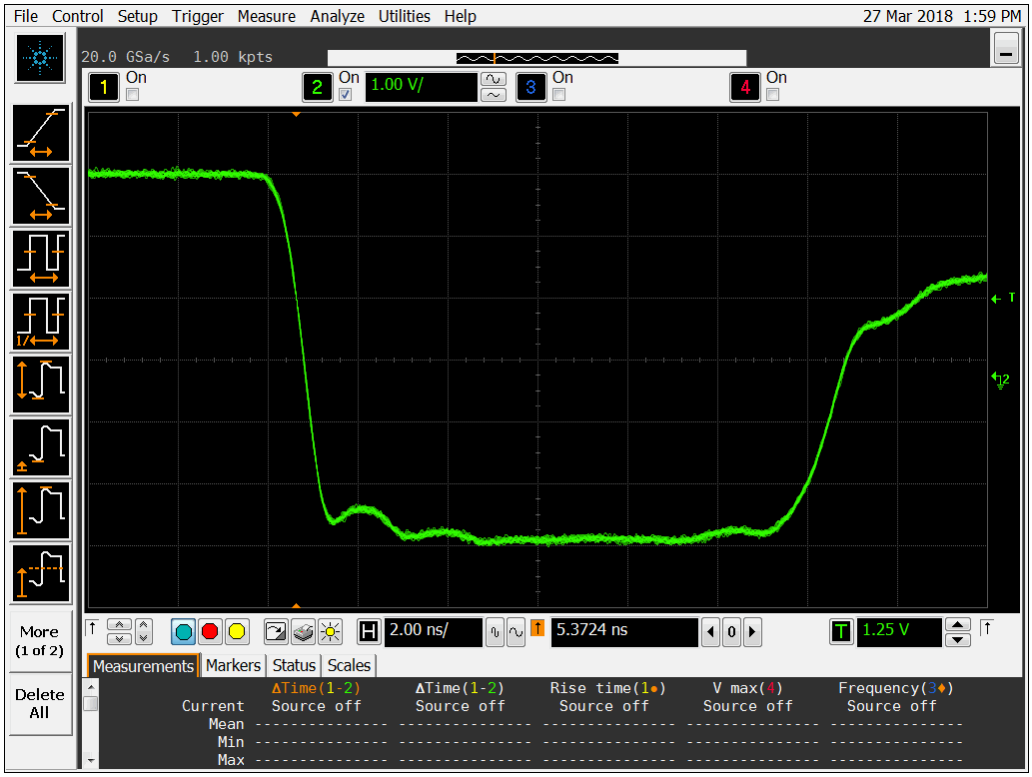


Figure 16a DUT 17207 Pre-Irradiation Falling Edge

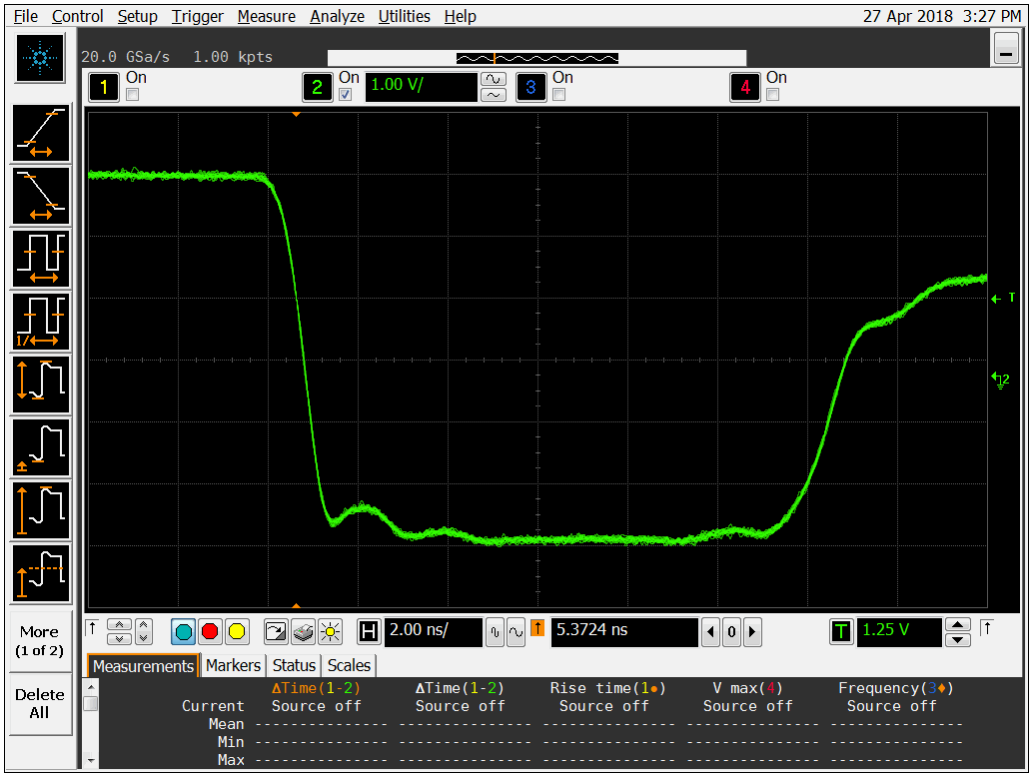


Figure 16b DUT 17207 Post-Annealing Falling Edge

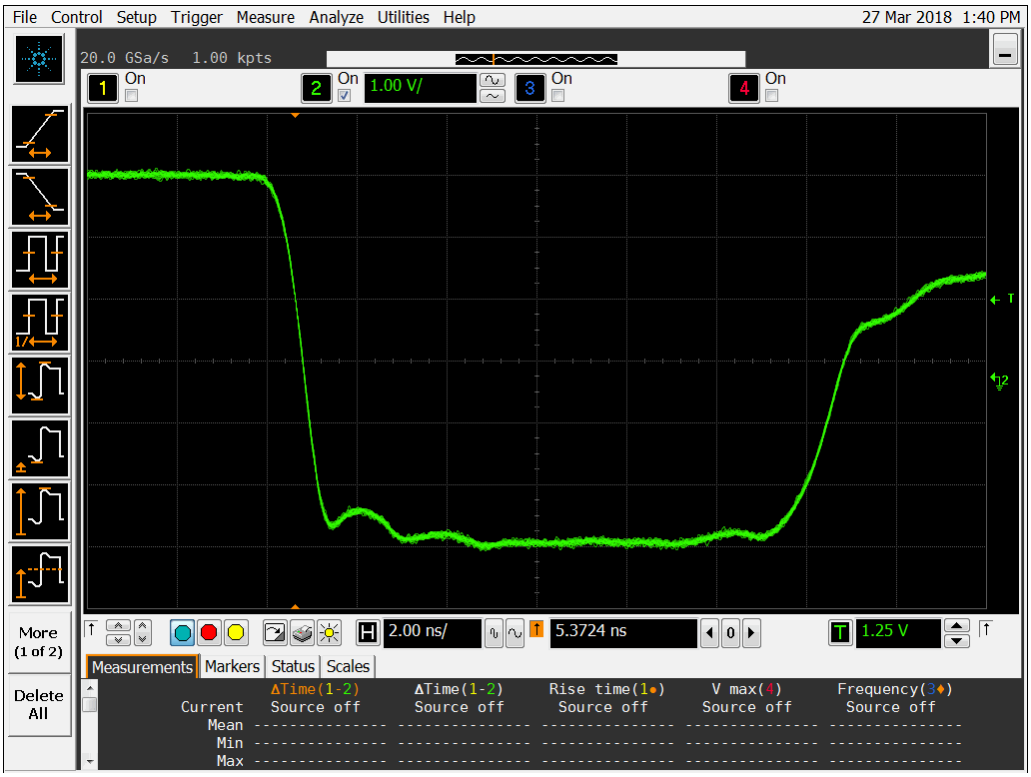


Figure 17a DUT 17182 Pre-Irradiation Falling Edge

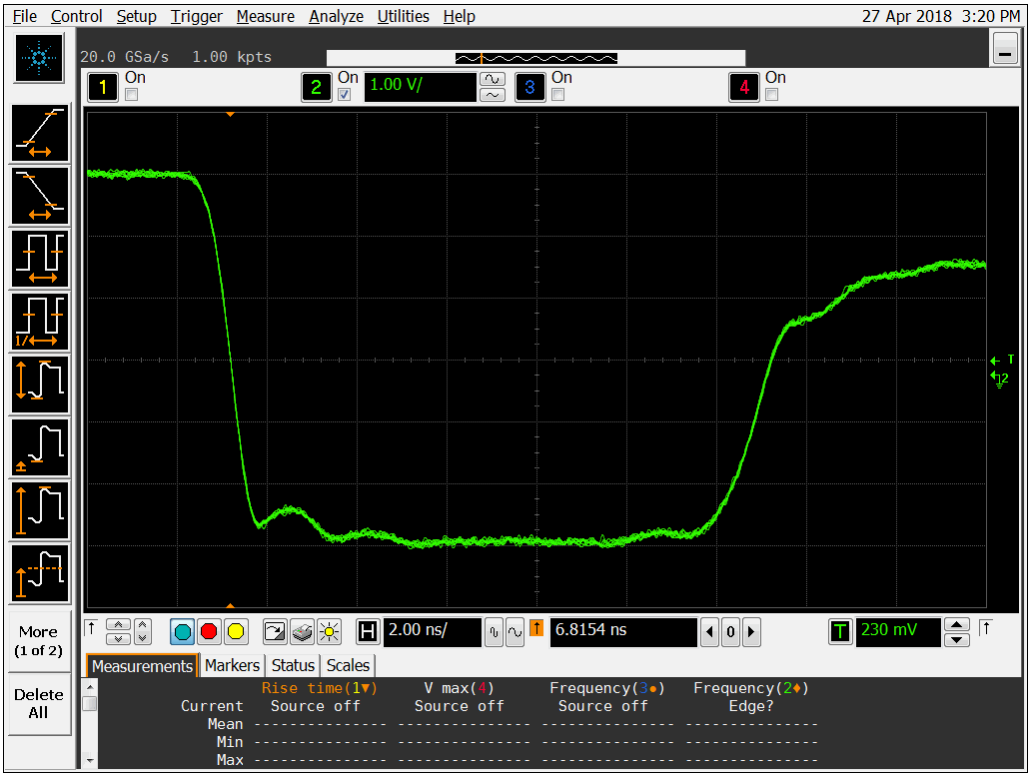


Figure 17b DUT 17182 Post-Annealing Falling Edge

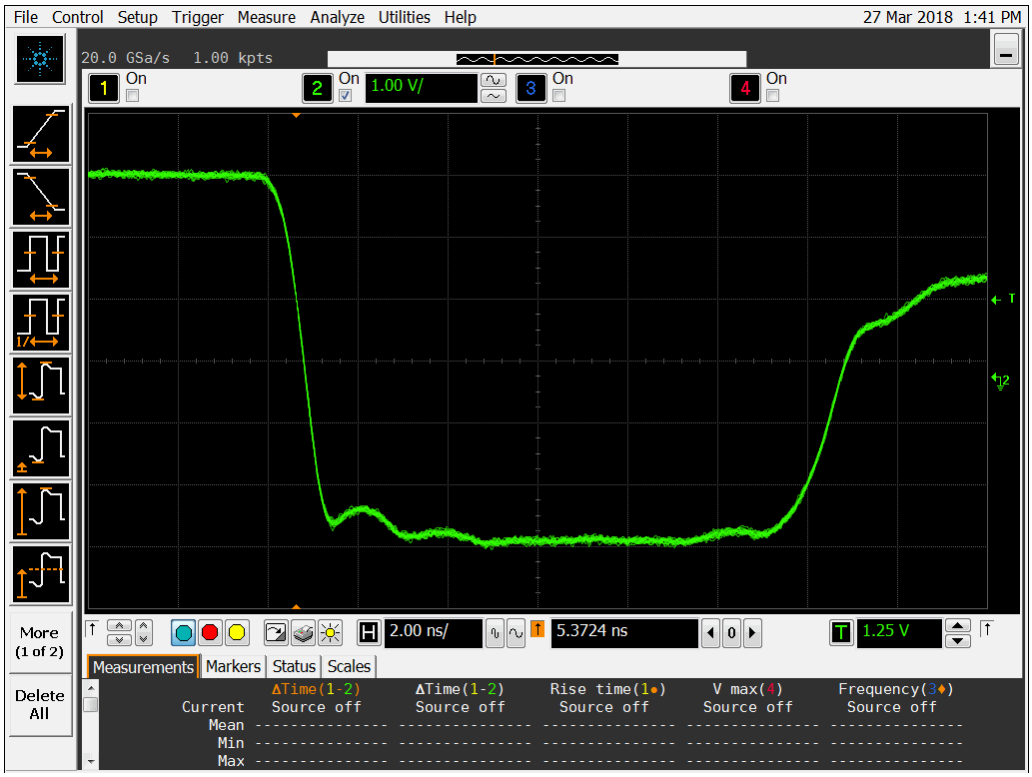


Figure 18a DUT 17183 Pre-Irradiation Falling Edge

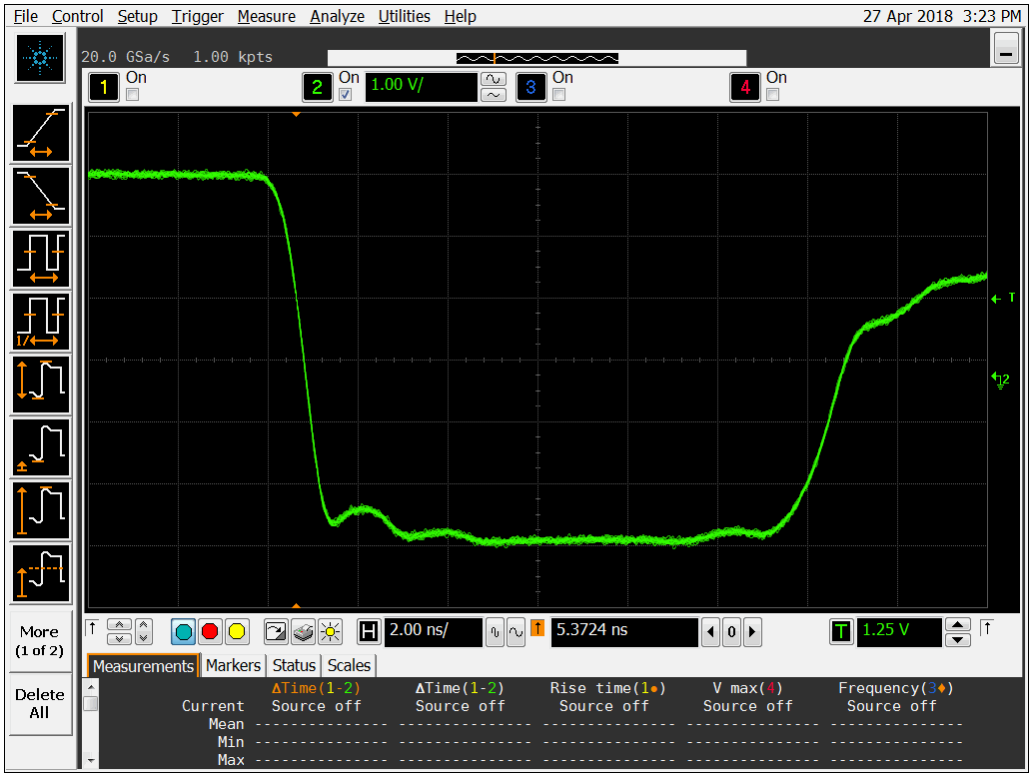


Figure 18b DUT 17183 Post-Annealing Falling Edge

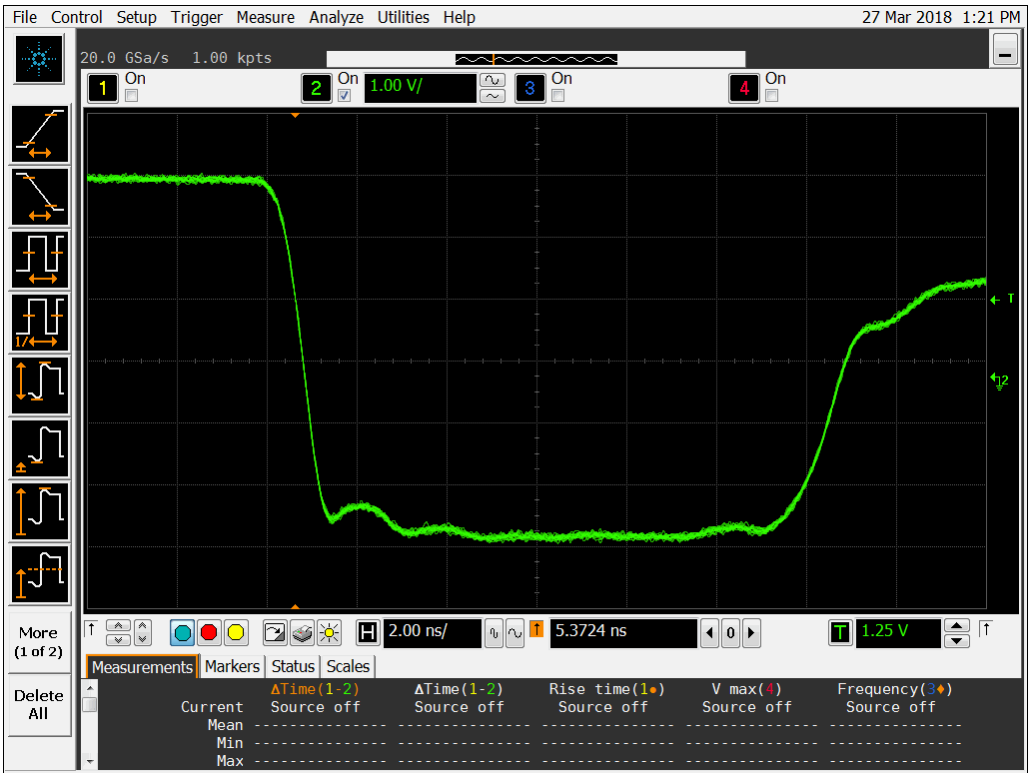


Figure 19a DUT 17175 Pre-Irradiation Falling Edge

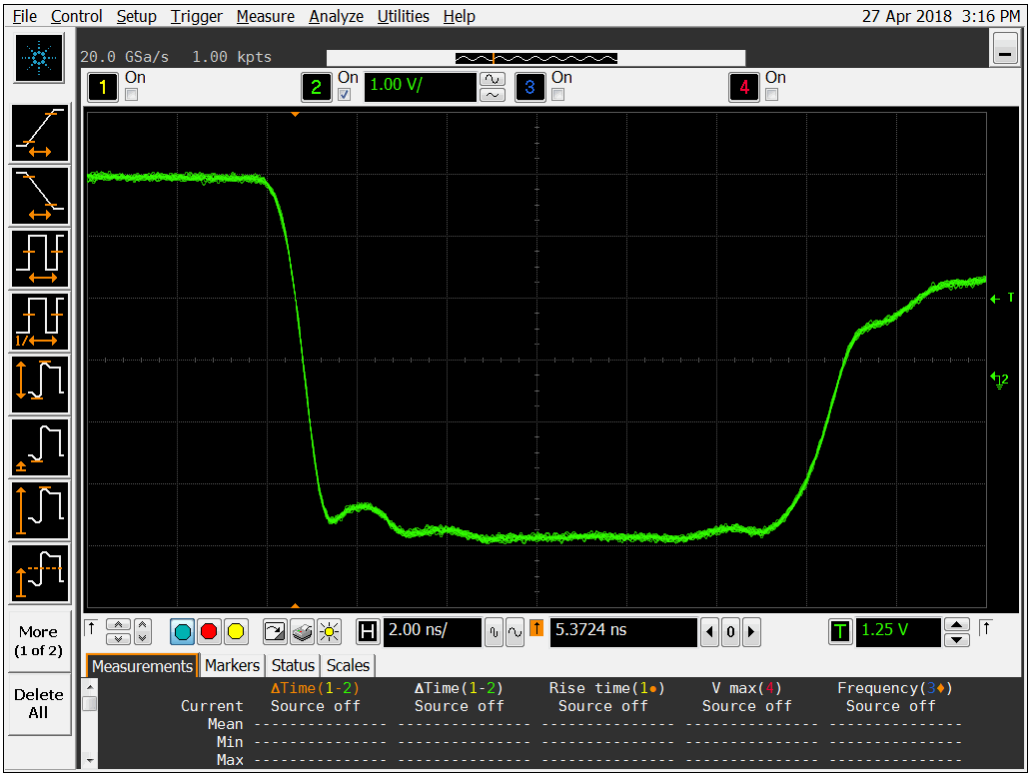


Figure 19b DUT 17175 Post-Annealing Falling Edge

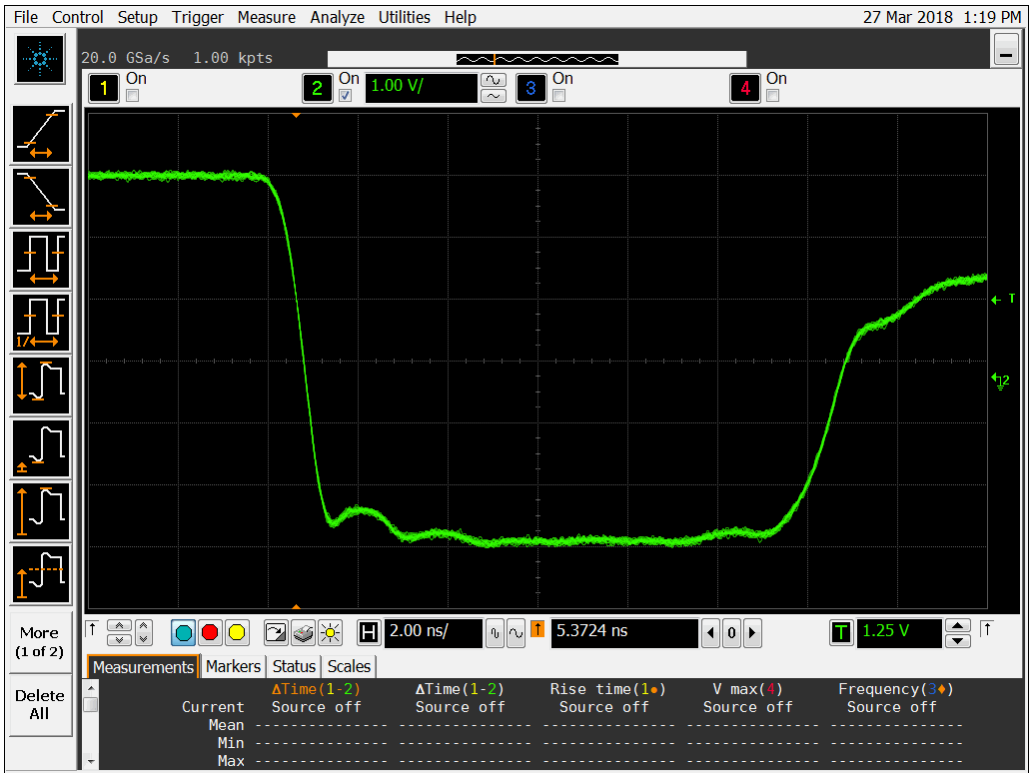


Figure 20a DUT 17179 Pre-Irradiation Falling Edge

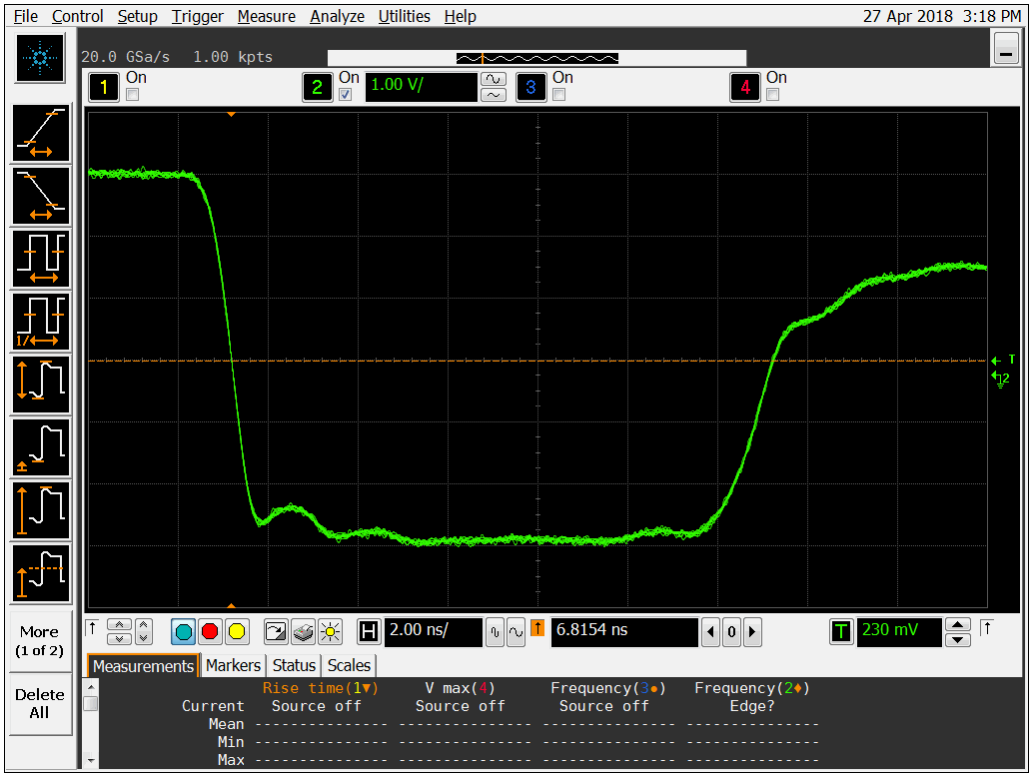


Figure 20b DUT 17179 Post-Annealing Falling Edge

Appendix A: DUT Bias

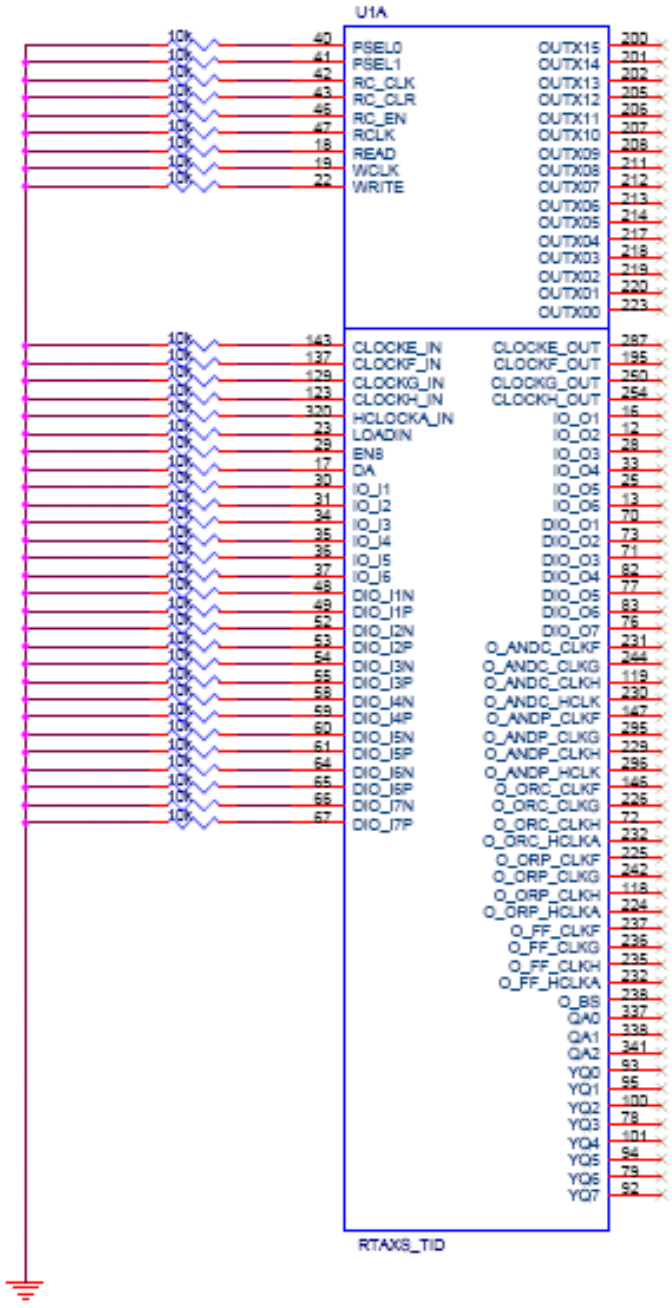


Figure A1 I/O Bias During Irradiation

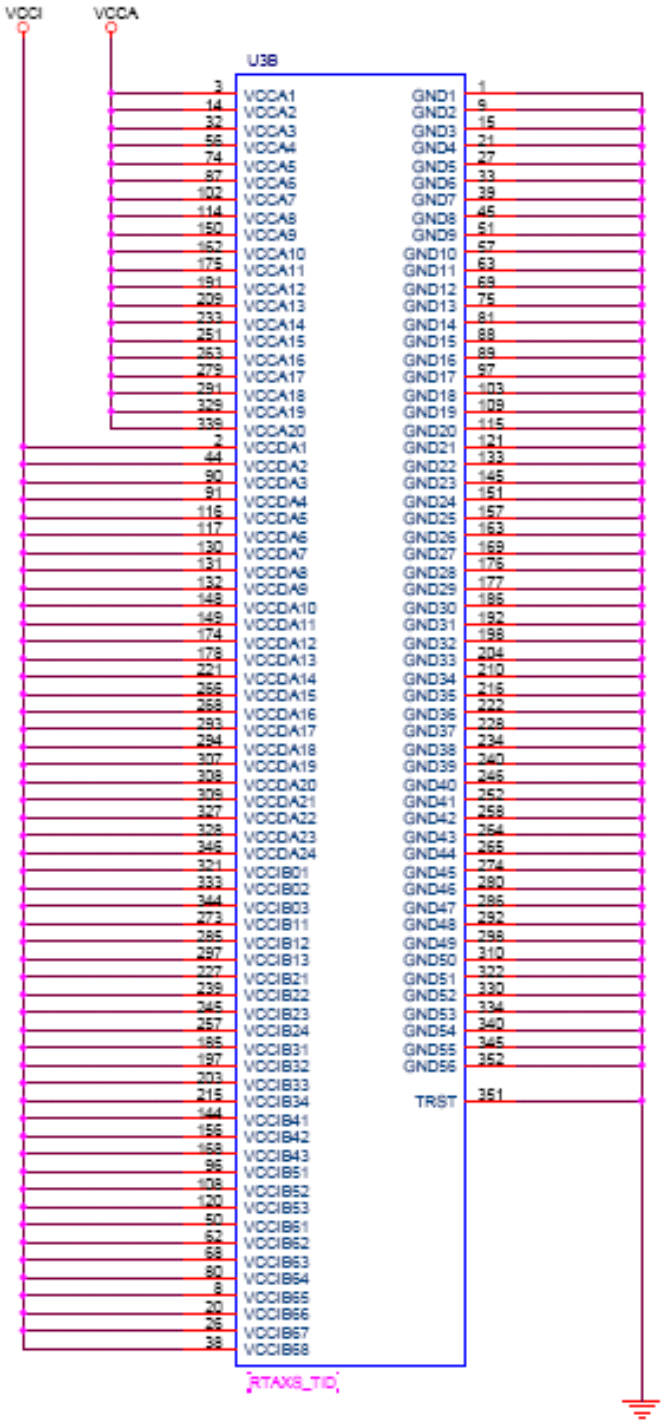
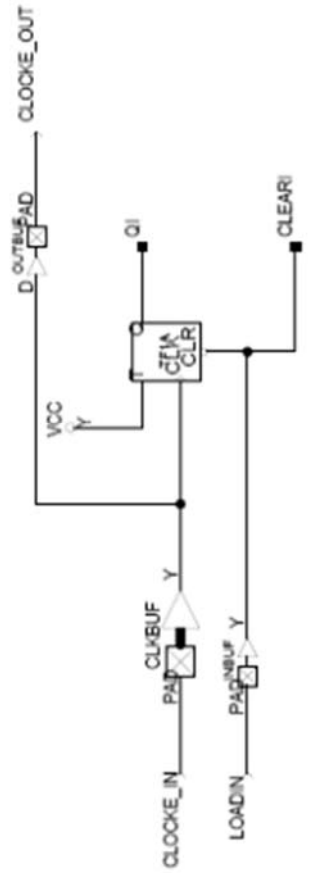
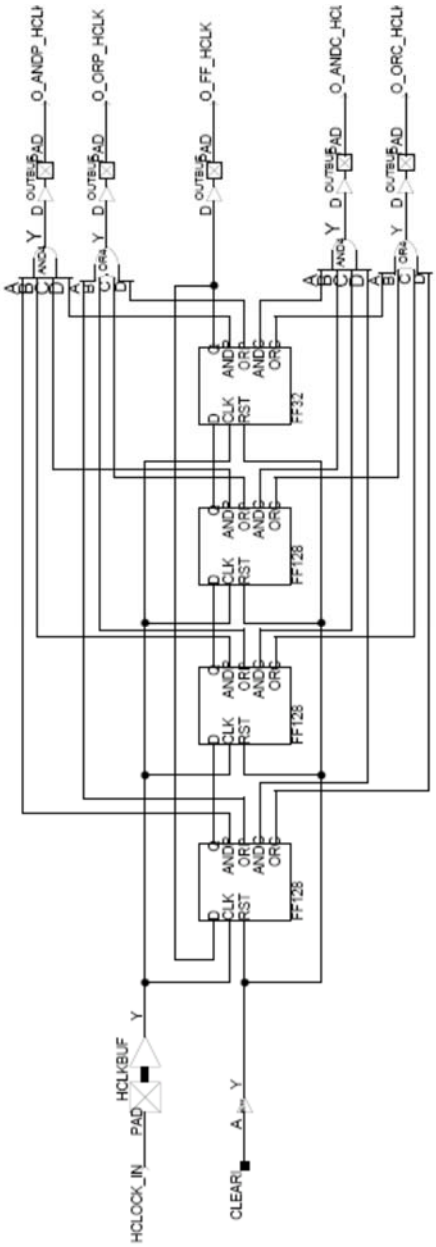


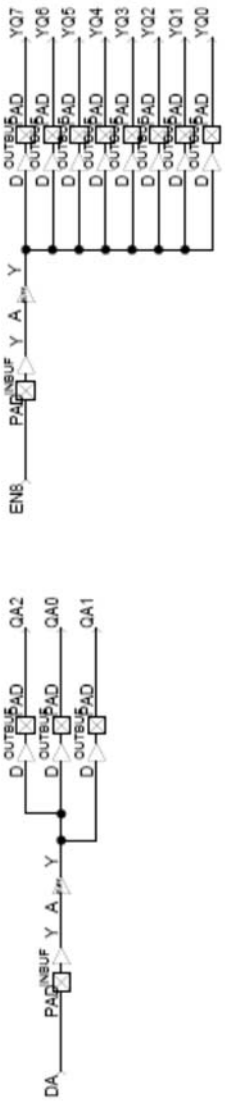
Figure A2 Power Supply, Ground and Special Pins Bias During Irradiation

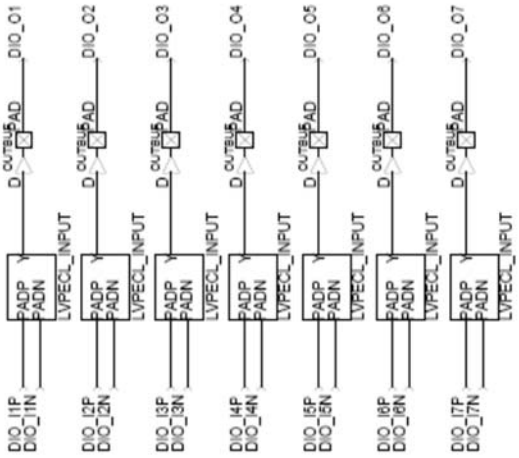
Appendix B: DUT Design Schematics and Verilog Files

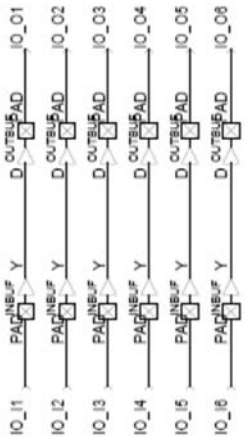


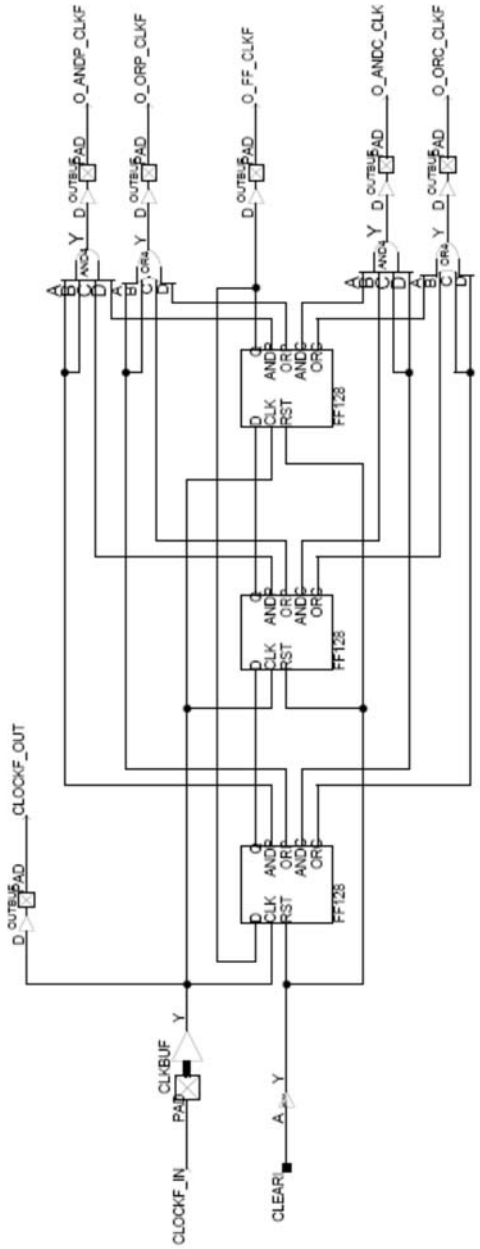

O_ANDP_HCLK
O_ORP_HCLK
O_FF_HCLK
O_ANDC_HCLK
O_ORC_HCLK
OUTBUF
PAD
AND4
OR4
FF32
FF128
HCLKBUF
HCLOCK_IN
CLEAR

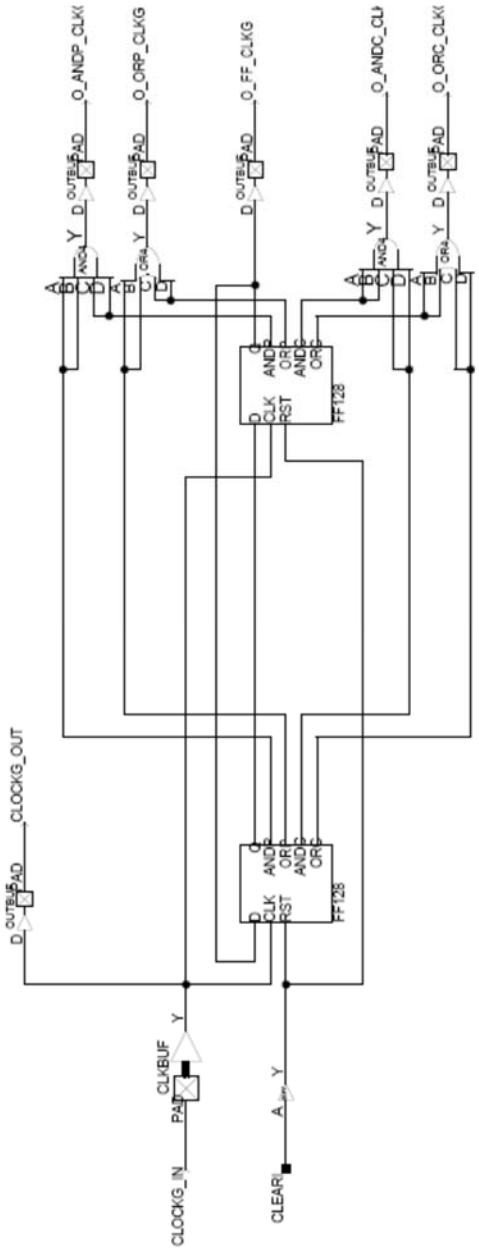

QI
In
Out
BUFF2p3k
D
OUTBUF
PAD
O_BS

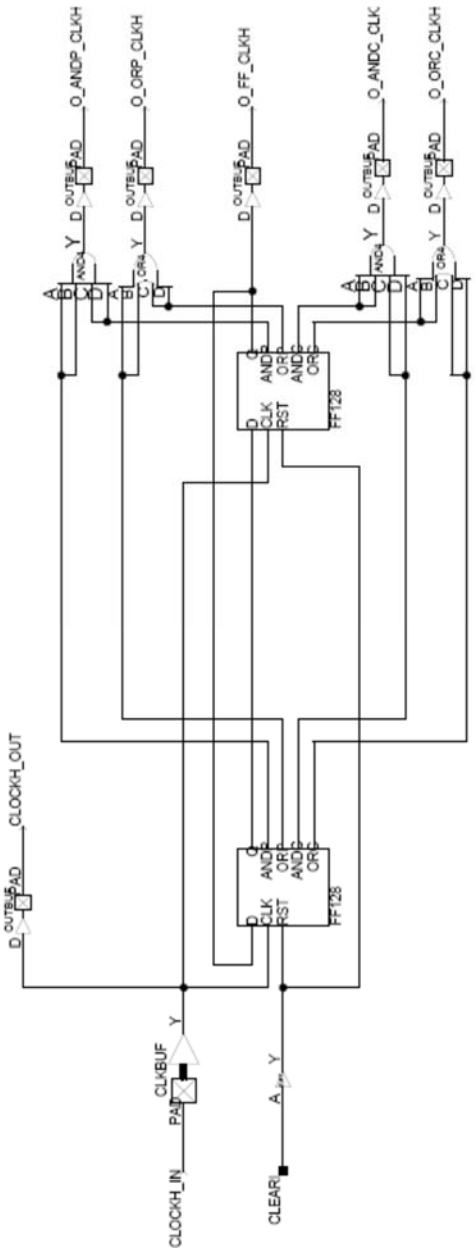

YQ7
YQ6
YQ5
YQ4
YQ3
YQ2
YQ1
YQ0
OUTBUF_PAD
D
Y
A
INBUF
PAD
EN8
QA2
QA0
QA1
DA


DIO_O1
DIO_O2
DIO_O3
DIO_O4
DIO_O5
DIO_O6
DIO_O7
OUTBUF
PAD
D
LVPECL_INPUT
PADP
PADN
Y
DIO_I1P
DIO_I1N
DIO_I2P
DIO_I2N
DIO_I3P
DIO_I3N
DIO_I4P
DIO_I4N
DIO_I5P
DIO_I5N
DIO_I6P
DIO_I6N
DIO_I7P
DIO_I7N


IO_O1
IO_O2
IO_O3
IO_O4
IO_O5
IO_O6
OUTBUF
PAD
D
PADINBUF
Y
IO_I1
IO_I2
IO_I3
IO_I4
IO_I5
IO_I6


O_ANDP_CLKF
O_ORP_CLKF
O_FF_CLKF
O_ANDC_CLK
O_ORC_CLKF
CLOCKF_OUT
CLKBUF
CLOCKF_IN
CLEAR


O_ANDP_CLKG
O_ORP_CLKG
O_FF_CLKG
O_ANDC_CLKG
O_ORC_CLKG
OUTBUF
PAD
D
Y
AND4
OR4
A
B
C
D
Q
ANDP
ORP
ANDC
ORC
CLK
RST
FF128
CLOCKG_OUT
CLKBUF
CLOCKG_IN
CLEAR


O_ANDP_CLKH
O_ORP_CLKH
O_FF_CLKH
O_ANDC_CLK
O_ORC_CLKH
OUTBUF
PAD
AND4
OR4
FF128
CLOCKH_OUT
CLKBUF
CLOCKH_IN
CLEAR

```
// BUFF2p3k.v
`timescale 1 ns/100 ps

module BUFF2p3k (In, Out);

input In;

output Out;

wire x1/*synthesis syn_keep=1 alspreserve=1*/;
wire x2/*synthesis syn_keep=1 alspreserve=1*/;
wire x3/*synthesis syn_keep=1 alspreserve=1*/;
wire x4/*synthesis syn_keep=1 alspreserve=1*/;
wire x5/*synthesis syn_keep=1 alspreserve=1*/;
wire x6/*synthesis syn_keep=1 alspreserve=1*/;
wire x7/*synthesis syn_keep=1 alspreserve=1*/;

BUFF1k buff1k_1 (.In(In), .Out(x1));
BUFF1k buff1k_2 (.In(x1), .Out(x2));
BUFF50 buff3 (.In(x2), .Out(x3));
BUFF50 buff4 (.In(x3), .Out(x4));
BUFF50 buff5 (.In(x4), .Out(x5));
BUFF50 buff6 (.In(x5), .Out(x6));
BUFF50 buff7 (.In(x6), .Out(x7));
BUFF50 buff8 (.In(x7), .Out(Out));

endmodule

// BUFF1k
`timescale 1 ns/100 ps

module BUFF1k (In, Out);

input In;

output Out;

wire x1/*synthesis syn_keep=1 alspreserve=1*/;
wire x2/*synthesis syn_keep=1 alspreserve=1*/;
wire x3/*synthesis syn_keep=1 alspreserve=1*/;
wire x4/*synthesis syn_keep=1 alspreserve=1*/;
wire x5/*synthesis syn_keep=1 alspreserve=1*/;
wire x6/*synthesis syn_keep=1 alspreserve=1*/;
wire x7/*synthesis syn_keep=1 alspreserve=1*/;
wire x8/*synthesis syn_keep=1 alspreserve=1*/;
wire x9/*synthesis syn_keep=1 alspreserve=1*/;
wire x10/*synthesis syn_keep=1 alspreserve=1*/;
wire x11/*synthesis syn_keep=1 alspreserve=1*/;
wire x12/*synthesis syn_keep=1 alspreserve=1*/;
wire x13/*synthesis syn_keep=1 alspreserve=1*/;
wire x14/*synthesis syn_keep=1 alspreserve=1*/;
wire x15/*synthesis syn_keep=1 alspreserve=1*/;
wire x16/*synthesis syn_keep=1 alspreserve=1*/;
wire x17/*synthesis syn_keep=1 alspreserve=1*/;
wire x18/*synthesis syn_keep=1 alspreserve=1*/;
wire x19/*synthesis syn_keep=1 alspreserve=1*/;
```

```
BUFF50 buff1 (.In(In), .Out(x1));
BUFF50 buff2 (.In(x1), .Out(x2));
BUFF50 buff3 (.In(x2), .Out(x3));
BUFF50 buff4 (.In(x3), .Out(x4));
BUFF50 buff5 (.In(x4), .Out(x5));
BUFF50 buff6 (.In(x5), .Out(x6));
BUFF50 buff7 (.In(x6), .Out(x7));
BUFF50 buff8 (.In(x7), .Out(x8));
BUFF50 buff9 (.In(x8), .Out(x9));
BUFF50 buff10 (.In(x9), .Out(x10));

BUFF50 buff11 (.In(x10), .Out(x11));
BUFF50 buff12 (.In(x11), .Out(x12));
BUFF50 buff13 (.In(x12), .Out(x13));
BUFF50 buff14 (.In(x13), .Out(x14));
BUFF50 buff15 (.In(x14), .Out(x15));
BUFF50 buff16 (.In(x15), .Out(x16));
BUFF50 buff17 (.In(x16), .Out(x17));
BUFF50 buff18 (.In(x17), .Out(x18));
BUFF50 buff19 (.In(x18), .Out(x19));
BUFF50 buff20 (.In(x19), .Out(Out));

endmodule

// BUFF50
`timescale 1 ns/100 ps

module BUFF50 (In, Out);

input In;

output Out;

wire x1 /*synthesis syn_keep=1 alspreserve=1*/;
wire x2 /*synthesis syn_keep=1 alspreserve=1*/;
wire x3 /*synthesis syn_keep=1 alspreserve=1*/;
wire x4 /*synthesis syn_keep=1 alspreserve=1*/;
wire x5 /*synthesis syn_keep=1 alspreserve=1*/;
wire x6/*synthesis syn_keep=1 alspreserve=1*/;
wire x7/*synthesis syn_keep=1 alspreserve=1*/;
wire x8/*synthesis syn_keep=1 alspreserve=1*/;
wire x9/*synthesis syn_keep=1 alspreserve=1*/;
wire x10/*synthesis syn_keep=1 alspreserve=1*/;
wire x11/*synthesis syn_keep=1 alspreserve=1*/;
wire x12/*synthesis syn_keep=1 alspreserve=1*/;
wire x13/*synthesis syn_keep=1 alspreserve=1*/;
wire x14/*synthesis syn_keep=1 alspreserve=1*/;
wire x15/*synthesis syn_keep=1 alspreserve=1*/;
wire x16/*synthesis syn_keep=1 alspreserve=1*/;
wire x17/*synthesis syn_keep=1 alspreserve=1*/;
wire x18/*synthesis syn_keep=1 alspreserve=1*/;
wire x19/*synthesis syn_keep=1 alspreserve=1*/;
wire x20/*synthesis syn_keep=1 alspreserve=1*/;
wire x21/*synthesis syn_keep=1 alspreserve=1*/;
wire x22/*synthesis syn_keep=1 alspreserve=1*/;
```

```
wire x23/*synthesis syn_keep=1 alspreserve=1*/;
wire x24/*synthesis syn_keep=1 alspreserve=1*/;
wire x25/*synthesis syn_keep=1 alspreserve=1*/;
wire x26/*synthesis syn_keep=1 alspreserve=1*/;
wire x27/*synthesis syn_keep=1 alspreserve=1*/;
wire x28/*synthesis syn_keep=1 alspreserve=1*/;
wire x29/*synthesis syn_keep=1 alspreserve=1*/;
wire x30/*synthesis syn_keep=1 alspreserve=1*/;
wire x31/*synthesis syn_keep=1 alspreserve=1*/;
wire x32/*synthesis syn_keep=1 alspreserve=1*/;
wire x33/*synthesis syn_keep=1 alspreserve=1*/;
wire x34/*synthesis syn_keep=1 alspreserve=1*/;
wire x35/*synthesis syn_keep=1 alspreserve=1*/;
wire x36/*synthesis syn_keep=1 alspreserve=1*/;
wire x37/*synthesis syn_keep=1 alspreserve=1*/;
wire x38/*synthesis syn_keep=1 alspreserve=1*/;
wire x39/*synthesis syn_keep=1 alspreserve=1*/;
wire x40/*synthesis syn_keep=1 alspreserve=1*/;
wire x41/*synthesis syn_keep=1 alspreserve=1*/;
wire x42/*synthesis syn_keep=1 alspreserve=1*/;
wire x43/*synthesis syn_keep=1 alspreserve=1*/;
wire x44/*synthesis syn_keep=1 alspreserve=1*/;
wire x45/*synthesis syn_keep=1 alspreserve=1*/;
wire x46/*synthesis syn_keep=1 alspreserve=1*/;
wire x47/*synthesis syn_keep=1 alspreserve=1*/;
wire x48/*synthesis syn_keep=1 alspreserve=1*/;
wire x49/*synthesis syn_keep=1 alspreserve=1*/;

BUFF buff1 (.A(In), .Y(x1));
BUFF buff2 (.A(x1), .Y(x2));
BUFF buff3 (.A(x2), .Y(x3));
BUFF buff4 (.A(x3), .Y(x4));
BUFF buff5 (.A(x4), .Y(x5));
BUFF buff6 (.A(x5), .Y(x6));
BUFF buff7 (.A(x6), .Y(x7));
BUFF buff8 (.A(x7), .Y(x8));
BUFF buff9 (.A(x8), .Y(x9));
BUFF buff10 (.A(x9), .Y(x10));

BUFF buff11 (.A(x10), .Y(x11));
BUFF buff12 (.A(x11), .Y(x12));
BUFF buff13 (.A(x12), .Y(x13));
BUFF buff14 (.A(x13), .Y(x14));
BUFF buff15 (.A(x14), .Y(x15));
BUFF buff16 (.A(x15), .Y(x16));
BUFF buff17 (.A(x16), .Y(x17));
BUFF buff18 (.A(x17), .Y(x18));
BUFF buff19 (.A(x18), .Y(x19));
BUFF buff20 (.A(x19), .Y(x20));

BUFF buff21 (.A(x20), .Y(x21));
BUFF buff22 (.A(x21), .Y(x22));
BUFF buff23 (.A(x22), .Y(x23));
BUFF buff24 (.A(x23), .Y(x24));
BUFF buff25 (.A(x24), .Y(x25));
BUFF buff26 (.A(x25), .Y(x26));
```

```
BUFF buff27 (.A(x26), .Y(x27));
BUFF buff28 (.A(x27), .Y(x28));
BUFF buff29 (.A(x28), .Y(x29));
BUFF buff30 (.A(x29), .Y(x30));

BUFF buff31 (.A(x30), .Y(x31));
BUFF buff32 (.A(x31), .Y(x32));
BUFF buff33 (.A(x32), .Y(x33));
BUFF buff34 (.A(x33), .Y(x34));
BUFF buff35 (.A(x34), .Y(x35));
BUFF buff36 (.A(x35), .Y(x36));
BUFF buff37 (.A(x36), .Y(x37));
BUFF buff38 (.A(x37), .Y(x38));
BUFF buff39 (.A(x38), .Y(x39));
BUFF buff40 (.A(x39), .Y(x40));

BUFF buff41 (.A(x40), .Y(x41));
BUFF buff42 (.A(x41), .Y(x42));
BUFF buff43 (.A(x42), .Y(x43));
BUFF buff44 (.A(x43), .Y(x44));
BUFF buff45 (.A(x44), .Y(x45));
BUFF buff46 (.A(x45), .Y(x46));
BUFF buff47 (.A(x46), .Y(x47));
BUFF buff48 (.A(x47), .Y(x48));
BUFF buff49 (.A(x48), .Y(x49));
BUFF buff50 (.A(x49), .Y(Out));

endmodule

// FF128
`timescale 1 ns/100 ps
module FF128 (D, Q, CLK, RST, ANDP, ORP, ANDC, ORC);

input D, CLK, RST;
output Q, ANDP, ORP, ANDC, ORC;

wire x1, x2, x3, Q;
wire andp_a, andp_b, andp_c, andp_d, orp_a, orp_b, orp_c, orp_d;
wire andc_a, andc_b, andc_c, andc_d, orc_a, orc_b, orc_c, orc_d;

FF32 dff_a (.D(D), .Q(x1), .CLK(CLK), .RST(RST), .ANDP(andp_a), .ORP(orp_a),
.ANDC(andc_a), .ORC(orc_a));

FF32 dff_b (.D(x1), .Q(x2), .CLK(CLK), .RST(RST), .ANDP(andp_b), .ORP(orp_b),
.ANDC(andc_b), .ORC(orc_b));

FF32 dff_c (.D(x2), .Q(x3), .CLK(CLK), .RST(RST), .ANDP(andp_c), .ORP(orp_c),
.ANDC(andc_c), .ORC(orc_c));

FF32 dff_d (.D(x3), .Q(Q), .CLK(CLK), .RST(RST), .ANDP(andp_d), .ORP(orp_d),
.ANDC(andc_d), .ORC(orc_d));

AND4 and4p (.A(andp_a), .B(andp_b), .C(andp_c), .D(andp_d), .Y(ANDP));
OR4 or4p (.A(orp_a), .B(orp_b), .C(orp_c), .D(orp_d), .Y(ORP));

AND4 and4c (.A(andc_a), .B(andc_b), .C(andc_c), .D(andc_d), .Y(ANDC));
```

```
OR4 or4c (.A(orc_a), .B(orc_b), .C(orc_c), .D(orc_d), .Y(ORC));

endmodule

// FF32
`timescale 1 ns/100 ps
module FF32 (D, Q, CLK, RST, ANDP, ORP, ANDC, ORC);

input D, CLK, RST;
output Q, ANDP, ORP, ANDC, ORC;

wire x1, x2, x3, Q;
wire andp_a, andp_b, andp_c, andp_d, orp_a, orp_b, orp_c, orp_d;
wire andc_a, andc_b, andc_c, andc_d, orc_a, orc_b, orc_c, orc_d;

FF8 dff_a (.D(D), .Q(x1), .CLK(CLK), .RST(RST), .ANDP(andp_a), .ORP(orp_a),
.ANDC(andc_a), .ORC(orc_a));

FF8 dff_b (.D(x1), .Q(x2), .CLK(CLK), .RST(RST), .ANDP(andp_b), .ORP(orp_b),
.ANDC(andc_b), .ORC(orc_b));

FF8 dff_c (.D(x2), .Q(x3), .CLK(CLK), .RST(RST), .ANDP(andp_c), .ORP(orp_c),
.ANDC(andc_c), .ORC(orc_c));

FF8 dff_d (.D(x3), .Q(Q), .CLK(CLK), .RST(RST), .ANDP(andp_d), .ORP(orp_d),
.ANDC(andc_d), .ORC(orc_d));

AND4 and4p (.A(andp_a), .B(andp_b), .C(andp_c), .D(andp_d), .Y(ANDP));
OR4 or4p (.A(orp_a), .B(orp_b), .C(orp_c), .D(orp_d), .Y(ORP));

AND4 and4c (.A(andc_a), .B(andc_b), .C(andc_c), .D(andc_d), .Y(ANDC));
OR4 or4c (.A(orc_a), .B(orc_b), .C(orc_c), .D(orc_d), .Y(ORC));

endmodule

// FF8
`timescale 1 ns/100 ps

module FF8 (D, Q, CLK, RST, ANDP, ORP, ANDC, ORC);

input D, CLK, RST;
output Q, ANDP, ORP, ANDC, ORC;

wire x1, x2, x3, x4, x5, x6, x7;

DFC1B dff1 (.D(D), .Q(x1), .CLK(CLK), .CLR(RST));
DFP1B dff2 (.D(x1), .Q(x2), .CLK(CLK), .PRE(RST));
DFC1B dff3 (.D(x2), .Q(x3), .CLK(CLK), .CLR(RST));
DFP1B dff4 (.D(x3), .Q(x4), .CLK(CLK), .PRE(RST));
DFC1B dff5 (.D(x4), .Q(x5), .CLK(CLK), .CLR(RST));
DFP1B dff6 (.D(x5), .Q(x6), .CLK(CLK), .PRE(RST));
DFC1B dff7 (.D(x6), .Q(x7), .CLK(CLK), .CLR(RST));
DFP1B dff8 (.D(x7), .Q(Q), .CLK(CLK), .PRE(RST));

AND4 and4p (.A(x2), .B(x4), .C(x6), .D(Q), .Y(ANDP));
OR4 or4p (.A(x2), .B(x4), .C(x6), .D(Q), .Y(ORP));
```

```
AND4 and4c (.A(x1), .B(x3), .C(x5), .D(x7), .Y(ANDC));
OR4 or4c (.A(x1), .B(x3), .C(x5), .D(x7), .Y(ORC));

endmodule

// Top_RAM_Module.v
`timescale 1 ns/100 ps

module Top_RAM_Module(Psel0, Psel1, RC_en, RC_clr, RC_clk, Write, Read, Wclk, Rclk,
                Q_RAM);
input Psel0, Psel1, RC_en, RC_clr, RC_clk, Write, Read, Wclk, Rclk;
output [5:0] Q_RAM;

wire Gnd, Vcc;
wire mx0, mx1;
wire [12:0] rc;
wire [3:0] dec;
wire y_0w, y_0r, y_1w, y_1r, y_2w, y_2r, y_3w, y_3r;
// y_4w, y_4r, y_5w, y_5r, y_6w, y_6r, y_7w, y_7r;
wire [5:0] DIN;
wire [5:0] Q_b0;
wire [5:0] Q_b1;
wire [5:0] Q_b2;
wire [5:0] Q_b3;
//wire [5:0] Q_b4;
//wire [5:0] Q_b5;
//wire [5:0] Q_b6;
//wire [5:0] Q_b7;

GND gnd_0(.Y(Gnd));
VCC vcc_0(.Y(Vcc));

mux_2x1 mux_0(.Data0_port(Gnd), .Data1_port(Vcc), .Sel0(Psel0), .Result(mx0));
mux_2x1 mux_1(.Data0_port(Gnd), .Data1_port(Vcc), .Sel0(Psel1), .Result(mx1));

counter_13 counter_0(.Enable(RC_en), .Aclr(RC_clr), .Clock(RC_clk), .Q(rc));

decoder_2to4 decoder_0(.Data0(rc[11]), .Data1(rc[12]), .Eq(dec));

NAND2 nand_0w(.A(dec[0]), .B(Write), .Y(y_0w));
NAND2 nand_0r(.A(dec[0]), .B(Read), .Y(y_0r));

ram_2048x6 ram_blk0(.Data(DIN), .Q(Q_b0), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_0w), .RE(y_0r), .WClock(Wclk), .RClock(Rclk));

assign DIN[0]=mx0, DIN[1]=mx1, DIN[2]=mx0, DIN[3]=mx1, DIN[4]=mx0, DIN[5]=mx1;

NAND2 nand_1w(.A(dec[1]), .B(Write), .Y(y_1w));
NAND2 nand_1r(.A(dec[1]), .B(Read), .Y(y_1r));

ram_2048x6 ram_blk1(.Data(DIN), .Q(Q_b1), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_1w), .RE(y_1r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_2w(.A(dec[2]), .B(Write), .Y(y_2w));
NAND2 nand_2r(.A(dec[2]), .B(Read), .Y(y_2r));
```

```
ram_2048x6 ram_blk2(.Data(DIN),
                .Q(Q_b2), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_2w), .RE(y_2r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_3w(.A(dec[3]), .B(Write), .Y(y_3w));
NAND2 nand_3r(.A(dec[3]), .B(Read), .Y(y_3r));

ram_2048x6 ram_blk3(.Data(DIN),
                .Q(Q_b3), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_3w), .RE(y_3r), .WClock(Wclk), .RClock(Rclk));

/* NAND2 nand_4w(.A(dec[4]), .B(Write), .Y(y_4w));
NAND2 nand_4r(.A(dec[4]), .B(Read), .Y(y_4r));

ram_2048x3 ram_blk4(.Data(DIN),
                .Q(Q_b4), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_4w), .RE(y_4r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_5w(.A(dec[5]), .B(Write), .Y(y_5w));
NAND2 nand_5r(.A(dec[5]), .B(Read), .Y(y_5r));

ram_2048x3 ram_blk5(.Data(DIN),
                .Q(Q_b5), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_5w), .RE(y_5r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_6w(.A(dec[6]), .B(Write), .Y(y_6w));
NAND2 nand_6r(.A(dec[6]), .B(Read), .Y(y_6r));

ram_2048x3 ram_blk6(.Data(DIN),
                .Q(Q_b6), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_6w), .RE(y_6r), .WClock(Wclk), .RClock(Rclk));

NAND2 nand_7w(.A(dec[7]), .B(Write), .Y(y_7w));
NAND2 nand_7r(.A(dec[7]), .B(Read), .Y(y_7r));

ram_2048x3 ram_blk7(.Data(DIN),
                .Q(Q_b7), .WAddress(rc[10:0]), .RAddress(rc[10:0]),
                .WE(y_7w), .RE(y_7r), .WClock(Wclk), .RClock(Rclk)); */

mux_6x4 mux_6x4_0(.Data0_port(Q_b0), .Data1_port(Q_b1), .Data2_port(Q_b2),
               .Data3_port(Q_b3), .Sel0(rc[11]),
               .Sel1(rc[12]), .Result(Q_RAM));

endmodule
```

```
`timescale 1 ns/100 ps
// Version: 6.0 SP3 6.0.30.3


module mux_2x1(Data0_port,Data1_port,Sel0,Result);
input Data0_port, Data1_port, Sel0;
output  Result;


    MX2 MX2_Result(.A(Data0_port), .B(Data1_port), .S(Sel0), .Y(
        Result));

endmodule

`timescale 1 ns/100 ps
// Version: 6.2 SP2 6.2.52.7


module counter_13(Enable,Aclr,Clock,Q);
input Enable, Aclr, Clock;
output [12:0] Q;

    wire ClrAux_0_net, ClrAux_7_net, MX2_1_Y, MX2_7_Y, MX2_4_Y,
        CM8_0_Y, MX2_10_Y, MX2_9_Y, MX2_3_Y, MX2_5_Y, MX2_6_Y,
        MX2_0_Y, MX2_8_Y, MX2_2_Y, MX2_11_Y, VCC, GND;

    VCC VCC_1_net(.Y(VCC));
    GND GND_1_net(.Y(GND));
    DFC1D DFC1D_Q_7_inst(.D(MX2_1_Y), .CLK(Q[6]), .CLR(
        ClrAux_7_net), .Q(Q[7]));
    DFC1D DFC1D_Q_1_inst(.D(MX2_7_Y), .CLK(Q[0]), .CLR(
        ClrAux_0_net), .Q(Q[1]));
    BUFF BUFF_ClrAux_0_inst(.A(Aclr), .Y(ClrAux_0_net));
    MX2 MX2_9(.A(VCC), .B(GND), .S(Q[5]), .Y(MX2_9_Y));
    DFC1D DFC1D_Q_2_inst(.D(MX2_6_Y), .CLK(Q[1]), .CLR(
        ClrAux_0_net), .Q(Q[2]));
    MX2 MX2_0(.A(VCC), .B(GND), .S(Q[8]), .Y(MX2_0_Y));
    DFC1D DFC1D_Q_12_inst(.D(MX2_4_Y), .CLK(Q[11]), .CLR(
        ClrAux_7_net), .Q(Q[12]));
    DFC1D DFC1D_Q_3_inst(.D(MX2_11_Y), .CLK(Q[2]), .CLR(
        ClrAux_0_net), .Q(Q[3]));
    DFC1D DFC1D_Q_4_inst(.D(MX2_5_Y), .CLK(Q[3]), .CLR(
        ClrAux_0_net), .Q(Q[4]));
    CM8 CM8_0(.D0(GND), .D1(VCC), .D2(VCC), .D3(GND), .S00(Q[0]),
        .S01(VCC), .S10(Enable), .S11(GND), .Y(CM8_0_Y));
    MX2 MX2_11(.A(VCC), .B(GND), .S(Q[3]), .Y(MX2_11_Y));
    DFC1B DFC1B_Q_0_inst(.D(CM8_0_Y), .CLK(Clock), .CLR(
        ClrAux_0_net), .Q(Q[0]));
    MX2 MX2_6(.A(VCC), .B(GND), .S(Q[2]), .Y(MX2_6_Y));
    MX2 MX2_3(.A(VCC), .B(GND), .S(Q[10]), .Y(MX2_3_Y));
    DFC1D DFC1D_Q_11_inst(.D(MX2_10_Y), .CLK(Q[10]), .CLR(
        ClrAux_7_net), .Q(Q[11]));
    MX2 MX2_10(.A(VCC), .B(GND), .S(Q[11]), .Y(MX2_10_Y));
    BUFF BUFF_ClrAux_7_inst(.A(Aclr), .Y(ClrAux_7_net));
    MX2 MX2_4(.A(VCC), .B(GND), .S(Q[12]), .Y(MX2_4_Y));
    DFC1D DFC1D_Q_5_inst(.D(MX2_9_Y), .CLK(Q[4]), .CLR(
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      ClrAux_0_net), .Q(Q[5]));
   DFC1D DFC1D_Q_9_inst(.D(MX2_8_Y), .CLK(Q[8]), .CLR(
      ClrAux_7_net), .Q(Q[9]));
   MX2 MX2_5(.A(VCC), .B(GND), .S(Q[4]), .Y(MX2_5_Y));
   MX2 MX2_8(.A(VCC), .B(GND), .S(Q[9]), .Y(MX2_8_Y));
   DFC1D DFC1D_Q_8_inst(.D(MX2_0_Y), .CLK(Q[7]), .CLR(
      ClrAux_7_net), .Q(Q[8]));
   MX2 MX2_2(.A(VCC), .B(GND), .S(Q[6]), .Y(MX2_2_Y));
   MX2 MX2_7(.A(VCC), .B(GND), .S(Q[1]), .Y(MX2_7_Y));
   MX2 MX2_1(.A(VCC), .B(GND), .S(Q[7]), .Y(MX2_1_Y));
   DFC1D DFC1D_Q_6_inst(.D(MX2_2_Y), .CLK(Q[5]), .CLR(
      ClrAux_0_net), .Q(Q[6]));
   DFC1D DFC1D_Q_10_inst(.D(MX2_3_Y), .CLK(Q[9]), .CLR(
      ClrAux_7_net), .Q(Q[10]));

endmodule

`timescale 1 ns/100 ps
// Version: 6.2 SP2 6.2.52.7


module decoder_2to4(Data0,Data1,Eq);
input Data0, Data1;
output [3:0] Eq;


   AND2A AND2A_Eq_1_inst(.A(Data1), .B(Data0), .Y(Eq[1]));
   AND2 AND2_Eq_3_inst(.A(Data0), .B(Data1), .Y(Eq[3]));
   AND2A AND2A_Eq_2_inst(.A(Data0), .B(Data1), .Y(Eq[2]));
   AND2B AND2B_Eq_0_inst(.A(Data0), .B(Data1), .Y(Eq[0]));

endmodule

`timescale 1 ns/100 ps
// Version: 6.2 SP2 6.2.52.7


module ram_2048x6(Data,Q,WAddress,RAddress,WE,RE,WClock,RClock);
input [5:0] Data;
output [5:0] Q;
input [10:0] WAddress, RAddress;
input WE, RE, WClock, RClock;

   wire WEP, REP, VCC, GND;

   VCC VCC_1_net(.Y(VCC));
   GND GND_1_net(.Y(GND));
   RAM64K36P ram_2048x6_R0C2(.WCLK(WClock), .RCLK(RClock),
      .DEPTH0(GND), .DEPTH1(GND), .DEPTH2(GND), .DEPTH3(GND),
      .WEN(WEP), .WW0(VCC), .WW1(GND), .WW2(GND), .WRAD0(
      WAddress[0]), .WRAD1(WAddress[1]), .WRAD2(WAddress[2]),
      .WRAD3(WAddress[3]), .WRAD4(WAddress[4]), .WRAD5(
      WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),
      .WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(
      WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),
      .WRAD14(GND), .WRAD15(GND), .WD0(Data[4]), .WD1(Data[5]),
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    .WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),
    .WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),
    .WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND)
    , .WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(
    GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),
    .WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)
    , .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(
    GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(
    RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),
    .RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(
    RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),
    .RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(
    RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),
    .RDAD14(GND), .RDAD15(GND), .RD0(Q[4]), .RD1(Q[5]), .RD2()
    , .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),
    .RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),
    .RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),
    .RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),
    .RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),
    .RD34(), .RD35());
  INV REBUBBLE(.A(RE), .Y(REP));
  INV WEBUBBLE(.A(WE), .Y(WEP));
  RAM64K36P ram_2048x6_R0C1(.WCLK(WClock), .RCLK(RClock),
    .DEPTH0(GND), .DEPTH1(GND), .DEPTH2(GND), .DEPTH3(GND),
    .WEN(WEP), .WW0(VCC), .WW1(GND), .WW2(GND), .WRAD0(
    WAddress[0]), .WRAD1(WAddress[1]), .WRAD2(WAddress[2]),
    .WRAD3(WAddress[3]), .WRAD4(WAddress[4]), .WRAD5(
    WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),
    .WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(
    WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),
    .WRAD14(GND), .WRAD15(GND), .WD0(Data[2]), .WD1(Data[3]),
    .WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),
    .WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),
    .WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND)
    , .WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(
    GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),
    .WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)
    , .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(
    GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(
    RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),
    .RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(
    RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),
    .RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(
    RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),
    .RDAD14(GND), .RDAD15(GND), .RD0(Q[2]), .RD1(Q[3]), .RD2()
    , .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),
    .RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),
    .RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),
    .RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),
    .RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),
    .RD34(), .RD35());
  RAM64K36P ram_2048x6_R0C0(.WCLK(WClock), .RCLK(RClock),
    .DEPTH0(GND), .DEPTH1(GND), .DEPTH2(GND), .DEPTH3(GND),
    .WEN(WEP), .WW0(VCC), .WW1(GND), .WW2(GND), .WRAD0(
    WAddress[0]), .WRAD1(WAddress[1]), .WRAD2(WAddress[2]),
    .WRAD3(WAddress[3]), .WRAD4(WAddress[4]), .WRAD5(
```

```
        WAddress[5]), .WRAD6(WAddress[6]), .WRAD7(WAddress[7]),
        .WRAD8(WAddress[8]), .WRAD9(WAddress[9]), .WRAD10(
        WAddress[10]), .WRAD11(GND), .WRAD12(GND), .WRAD13(GND),
        .WRAD14(GND), .WRAD15(GND), .WD0(Data[0]), .WD1(Data[1]),
        .WD2(GND), .WD3(GND), .WD4(GND), .WD5(GND), .WD6(GND),
        .WD7(GND), .WD8(GND), .WD9(GND), .WD10(GND), .WD11(GND),
        .WD12(GND), .WD13(GND), .WD14(GND), .WD15(GND), .WD16(GND)
        , .WD17(GND), .WD18(GND), .WD19(GND), .WD20(GND), .WD21(
        GND), .WD22(GND), .WD23(GND), .WD24(GND), .WD25(GND),
        .WD26(GND), .WD27(GND), .WD28(GND), .WD29(GND), .WD30(GND)
        , .WD31(GND), .WD32(GND), .WD33(GND), .WD34(GND), .WD35(
        GND), .REN(REP), .RW0(VCC), .RW1(GND), .RW2(GND), .RDAD0(
        RAddress[0]), .RDAD1(RAddress[1]), .RDAD2(RAddress[2]),
        .RDAD3(RAddress[3]), .RDAD4(RAddress[4]), .RDAD5(
        RAddress[5]), .RDAD6(RAddress[6]), .RDAD7(RAddress[7]),
        .RDAD8(RAddress[8]), .RDAD9(RAddress[9]), .RDAD10(
        RAddress[10]), .RDAD11(GND), .RDAD12(GND), .RDAD13(GND),
        .RDAD14(GND), .RDAD15(GND), .RD0(Q[0]), .RD1(Q[1]), .RD2()
        , .RD3(), .RD4(), .RD5(), .RD6(), .RD7(), .RD8(), .RD9(),
        .RD10(), .RD11(), .RD12(), .RD13(), .RD14(), .RD15(),
        .RD16(), .RD17(), .RD18(), .RD19(), .RD20(), .RD21(),
        .RD22(), .RD23(), .RD24(), .RD25(), .RD26(), .RD27(),
        .RD28(), .RD29(), .RD30(), .RD31(), .RD32(), .RD33(),
        .RD34(), .RD35());

endmodule

`timescale 1 ns/100 ps
// Version: 6.2 SP2 6.2.52.7

module mux_6x4(Data0_port,Data1_port,Data2_port,Data3_port,Sel0,
        Sel1,Result);
input [5:0] Data0_port, Data1_port, Data2_port, Data3_port;
input Sel0, Sel1;
output [5:0] Result;

    MX4 MX4_Result_0_inst(.D0(Data0_port[0]), .D1(Data1_port[0]),
       .D2(Data2_port[0]), .D3(Data3_port[0]), .S0(Sel0), .S1(
       Sel1), .Y(Result[0]));
    MX4 MX4_Result_2_inst(.D0(Data0_port[2]), .D1(Data1_port[2]),
       .D2(Data2_port[2]), .D3(Data3_port[2]), .S0(Sel0), .S1(
       Sel1), .Y(Result[2]));
    MX4 MX4_Result_5_inst(.D0(Data0_port[5]), .D1(Data1_port[5]),
       .D2(Data2_port[5]), .D3(Data3_port[5]), .S0(Sel0), .S1(
       Sel1), .Y(Result[5]));
    MX4 MX4_Result_1_inst(.D0(Data0_port[1]), .D1(Data1_port[1]),
       .D2(Data2_port[1]), .D3(Data3_port[1]), .S0(Sel0), .S1(
       Sel1), .Y(Result[1]));
    MX4 MX4_Result_4_inst(.D0(Data0_port[4]), .D1(Data1_port[4]),
       .D2(Data2_port[4]), .D3(Data3_port[4]), .S0(Sel0), .S1(
       Sel1), .Y(Result[4]));
    MX4 MX4_Result_3_inst(.D0(Data0_port[3]), .D1(Data1_port[3]),
       .D2(Data2_port[3]), .D3(Data3_port[3]), .S0(Sel0), .S1(
       Sel1), .Y(Result[3]));

endmodule
```



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